

# Nordic Conference on High Energy Physics, 4-7 January 2022

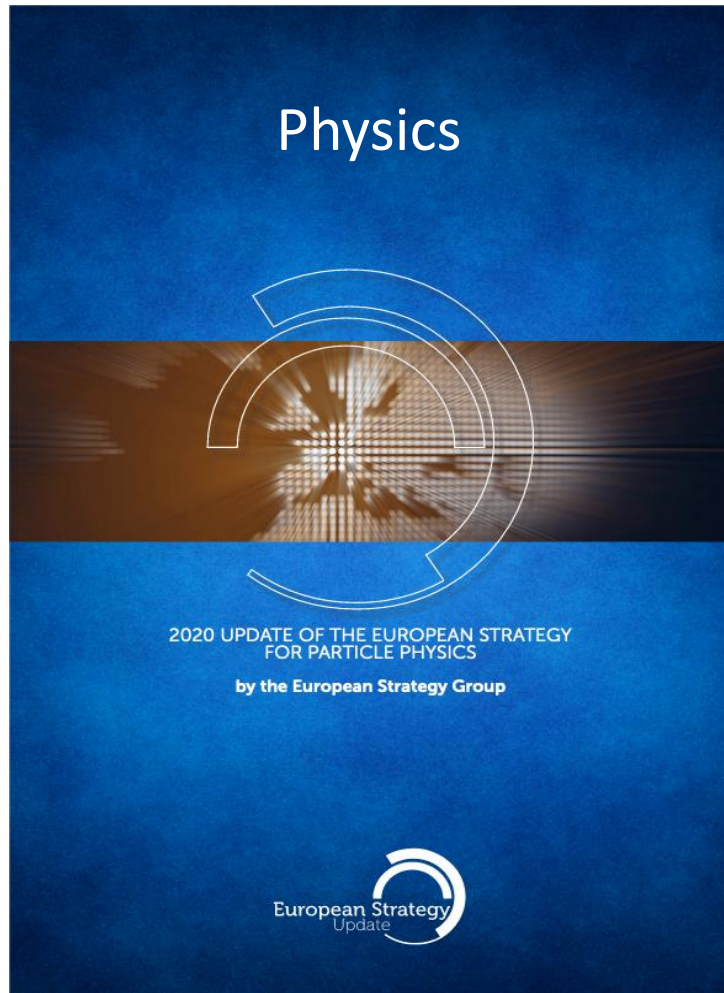
## Future experimental programs and detector R&D

D. Contardo, CNRS-IN2P3 IP2I

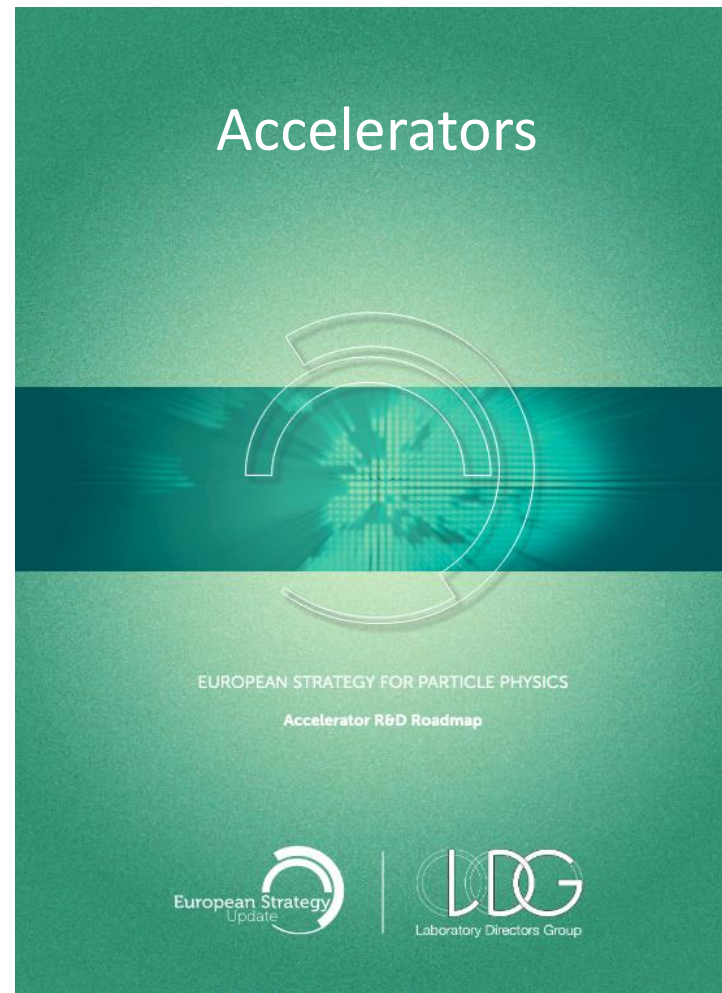




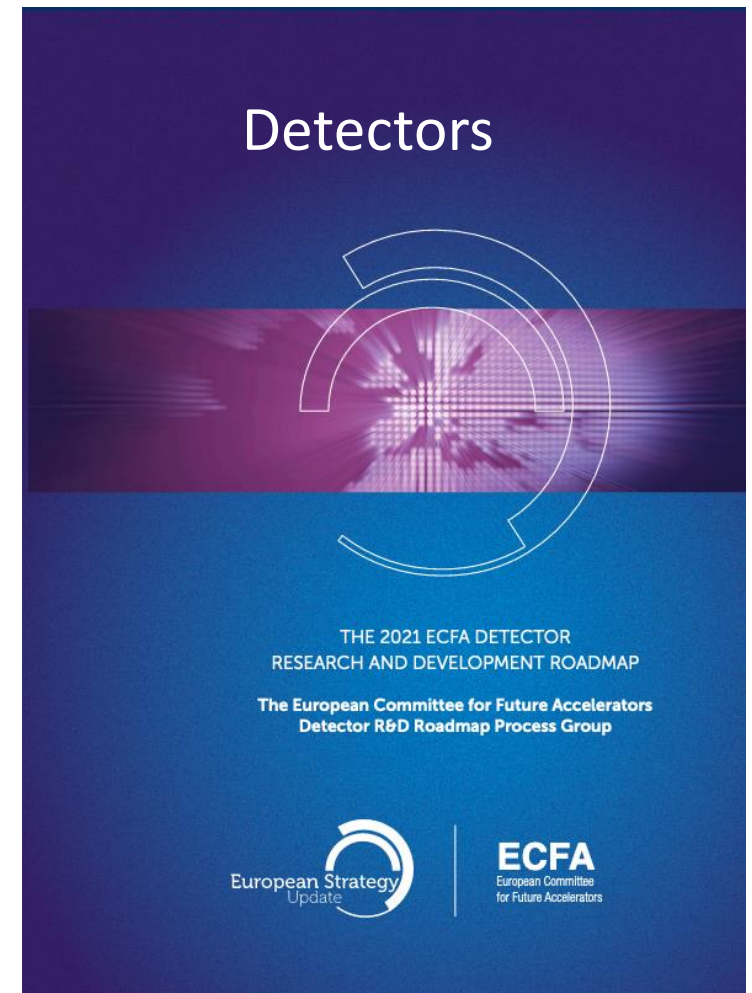
# European Strategy for Particle Physics update in 2020



<https://cds.cern.ch/record/2721370>  
<https://cds.cern.ch/record/2691414/files/1910.11775.pdf>



<https://cds.cern.ch/record/2800190>



<https://cds.cern.ch/record/2784893>

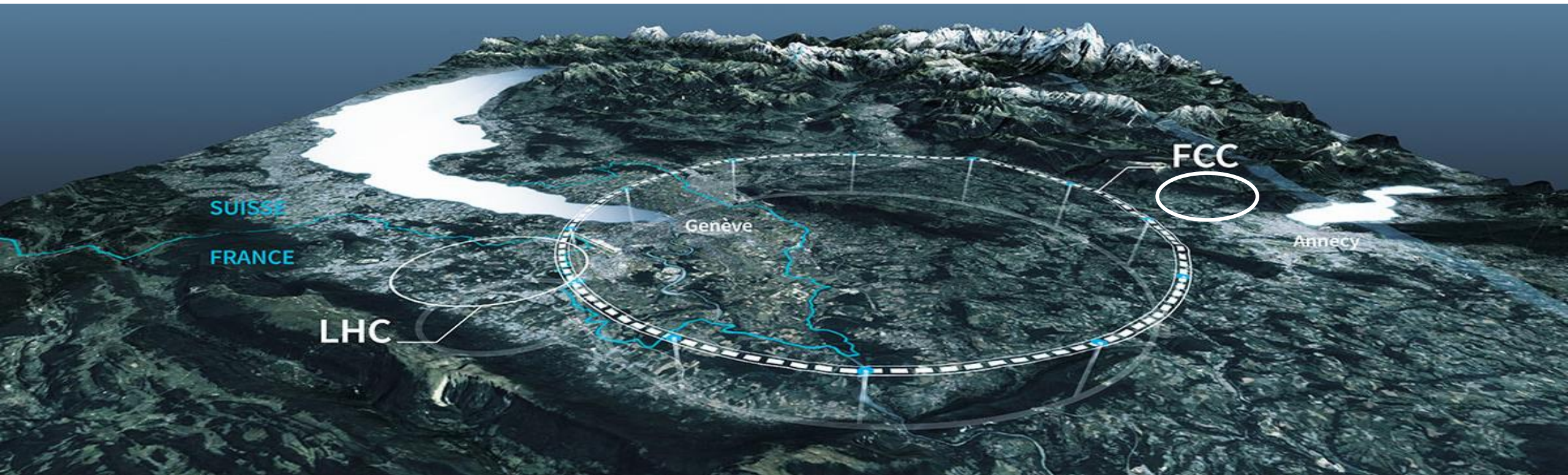
Snowmass strategy process in US <https://arxiv.org/pdf/2211.11084.pdf> 2022, P5 recommendation beginning of 2023



“ An electron-positron Higgs factory is the highest-priority next collider...”

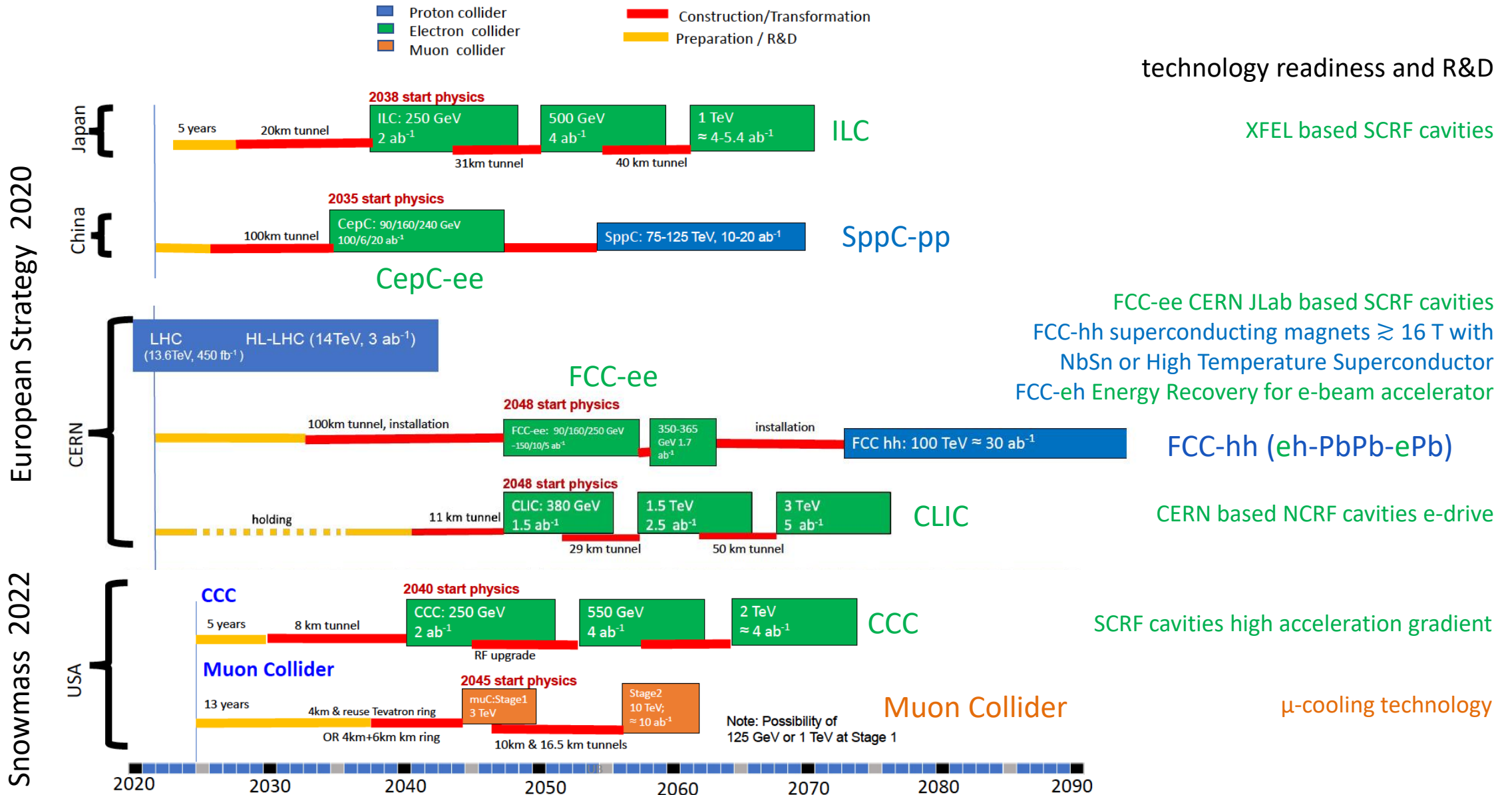
“Europe, together with its international partners, should investigate the technical and financial feasibility of a future hadron collider at CERN with a centre-of-mass energy of at least 100 TeV and with an electron-positron Higgs and electroweak factory as a possible first stage”

(European Strategy for Particle Physics <https://cds.cern.ch/record/2721370>)



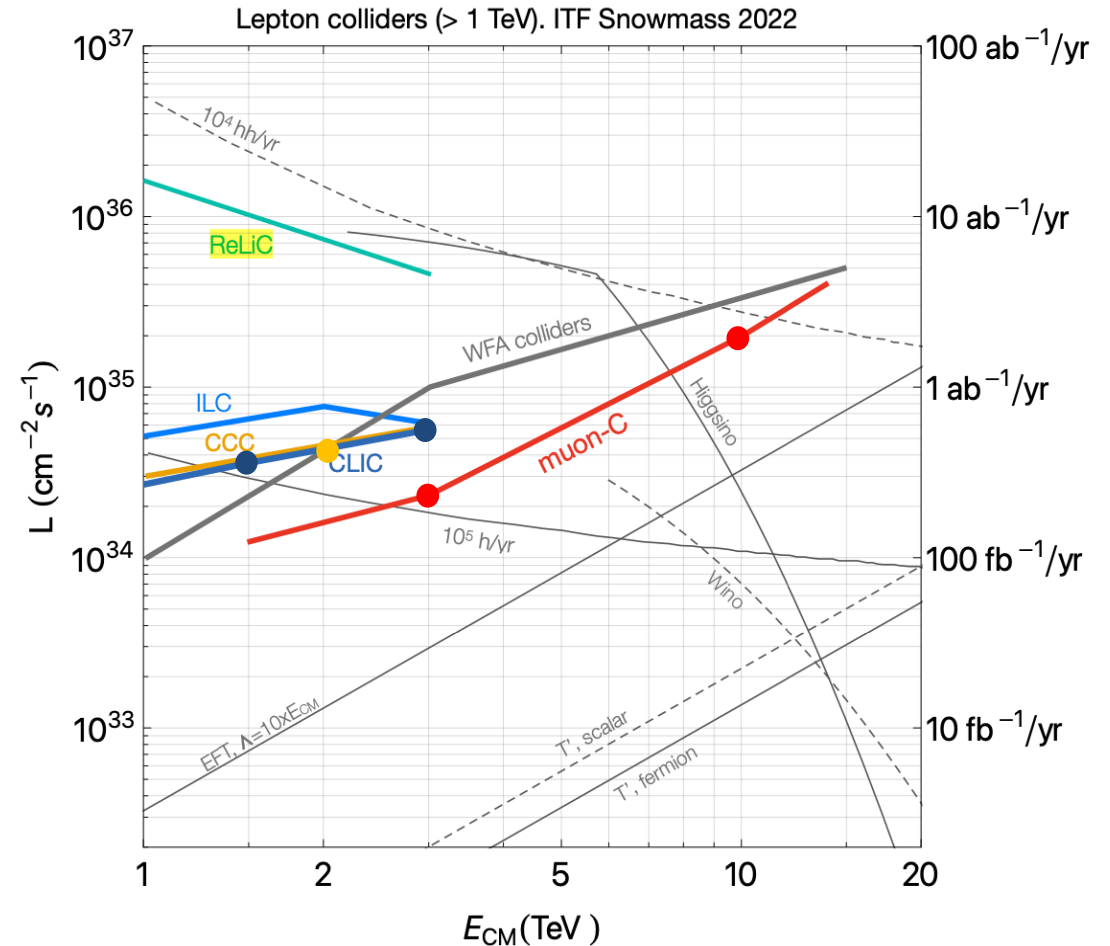
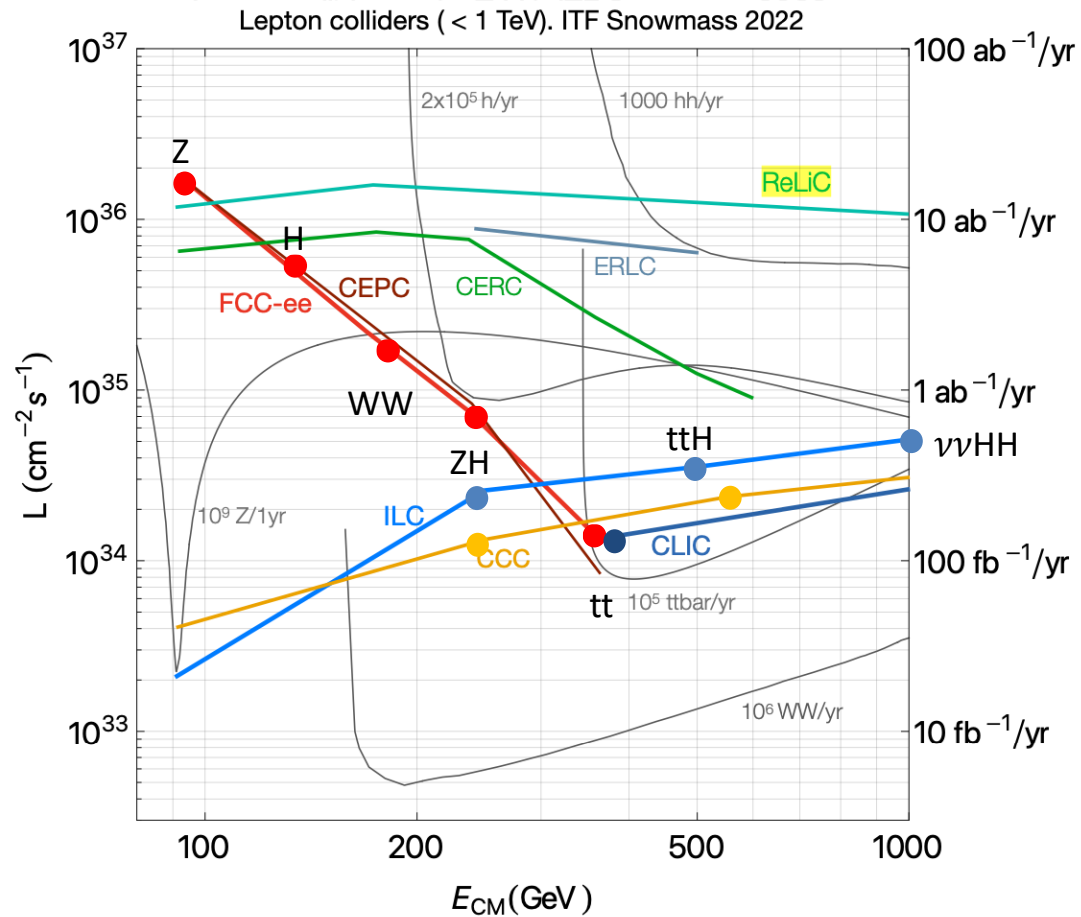
Future Circular Collider is an integrated physics program with e-e, h-h, e-h, Pb-Pb and e-Pb collisions  
a feasibility study report is expected end-2025 for the next ESPP update and possibly a decision

# Physics planning proposals for future colliders





# Lepton colliders luminosity and energy program\*



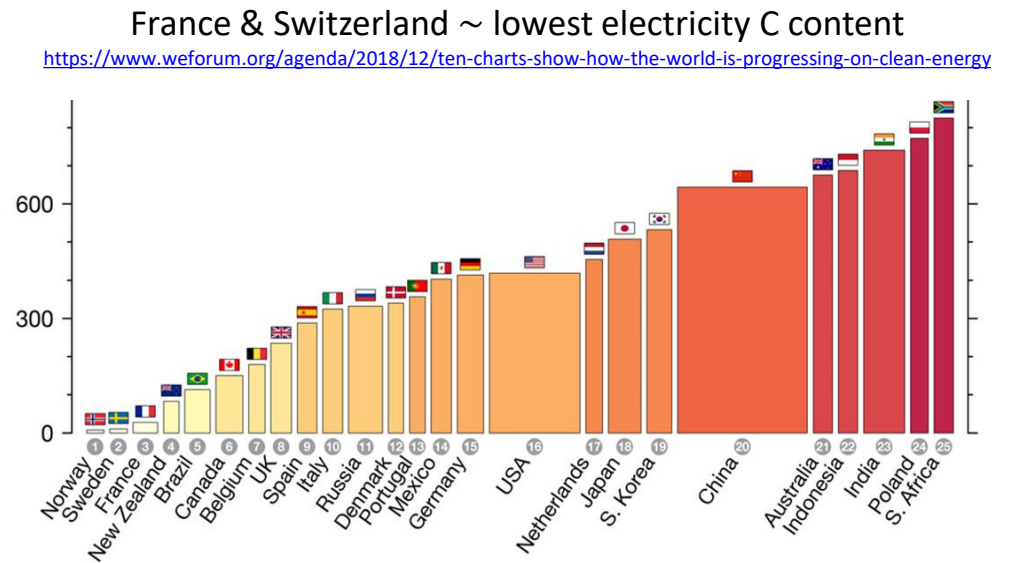
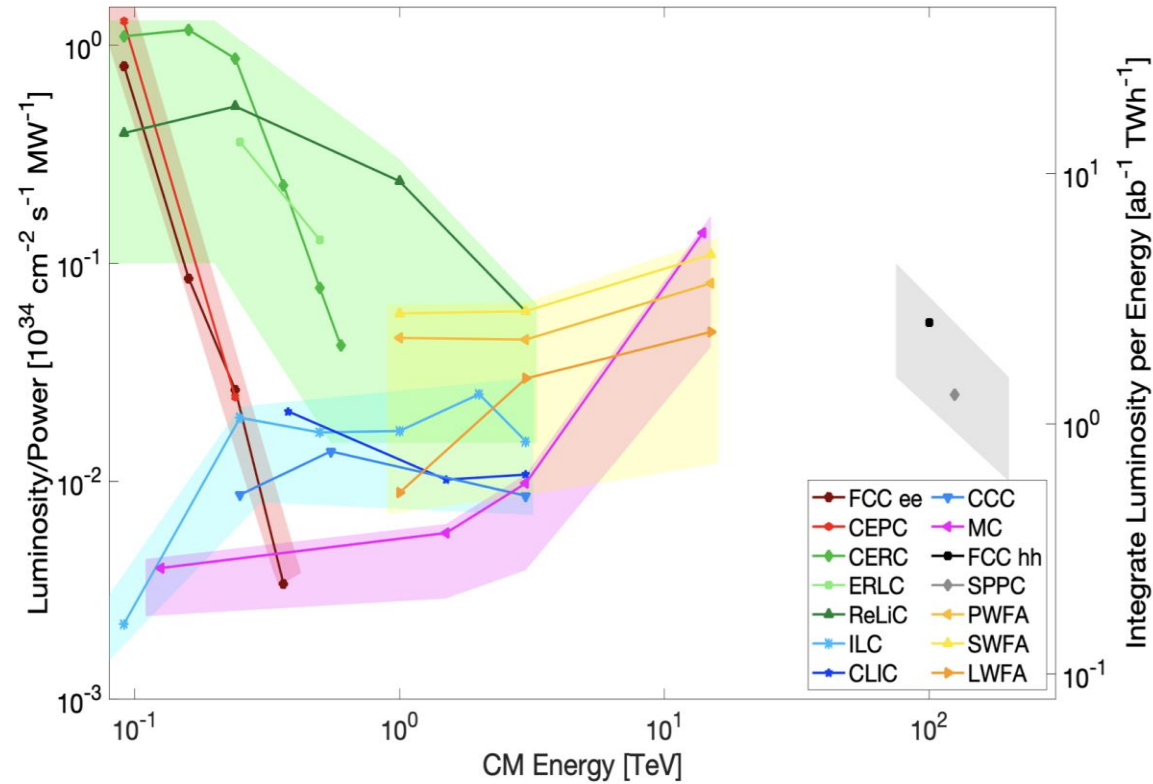
Energy recovery (CERC, ERLC, ReLiC), Wake Field (plasma) accelerators are at early R&D stage

\* Luminosities per IP, assuming  $10^7 \text{ s/ year}$  for integrated luminosity Snowmass strategy process in US <https://arxiv.org/abs/2208.06030>



# Sustainability

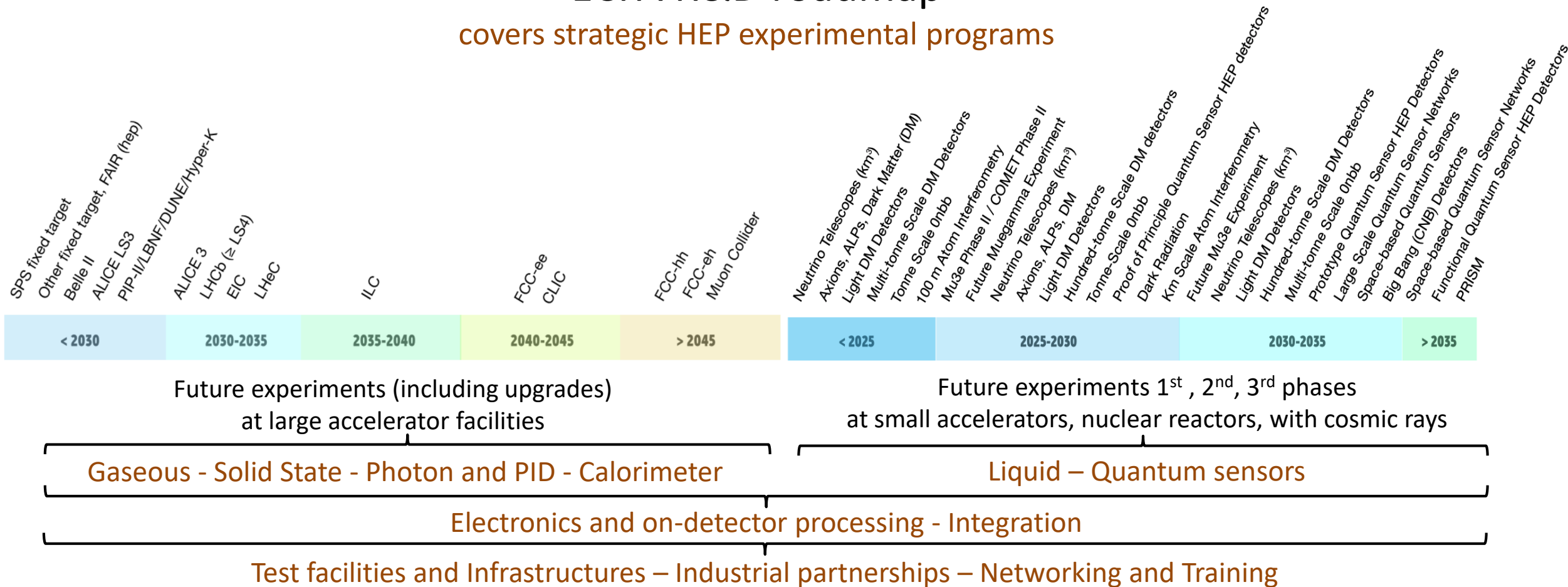
luminosity per electrical power figure of merit





# ECFA R&D roadmap

covers strategic HEP experimental programs

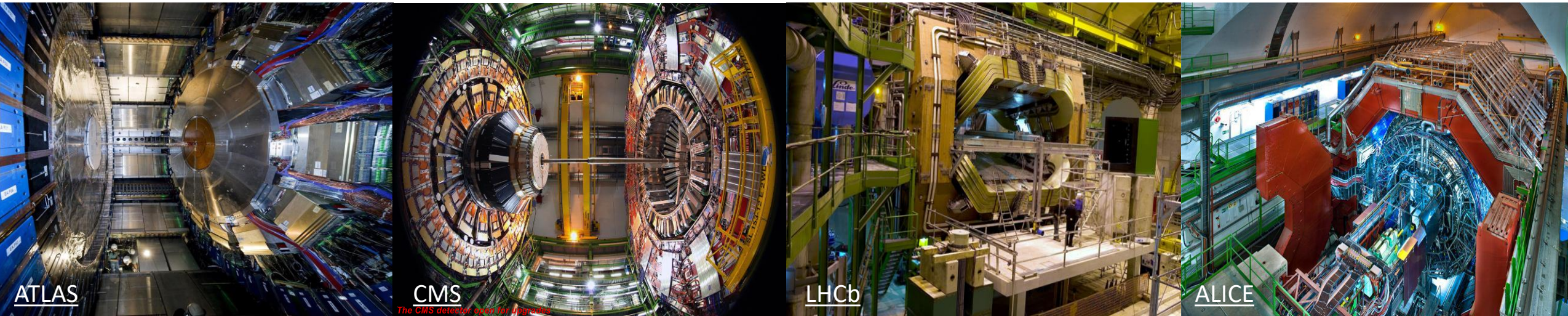


Nuclear Physics, AstroParticle (including Gravitational Wave) not considered, but NuPPEC and ApPEC invited to the process also joint ECFA - NuPPEC - ApPEC seminars in 2019 - 2022 to develop common instrumental projects



# Future Collider Detectors

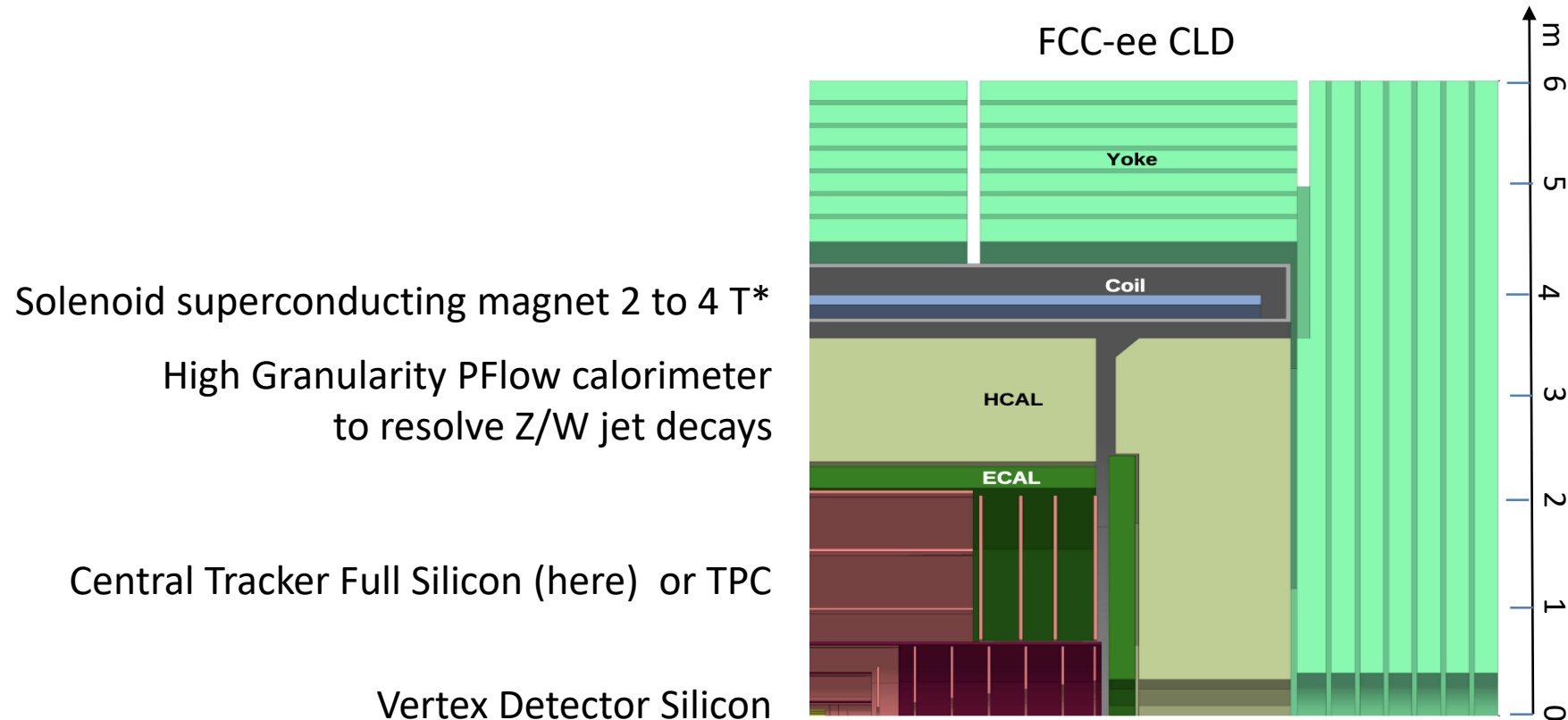
most constraining applications with R&D representative for several other projects



illustrations in the following mostly taken from LHC detectors above and/or State of the Art R&D

# Original detector concepts for $e^+e^-$ Higgs factory

ILD - SiD @ ILC, scaled to beam conditions @ CLICdet, then CEPC-BL/FST and FCC-ee CLD  
unprecedented tracking and hadron calorimetry precision



\* At FCC-ee the Z-pole B-field is limited to 2T (for high lumi.), also somehow setting tracker radius at 2m, calorimeters are  $22 X/X_0$  and  $7 \lambda$  with depth driven by absorbers



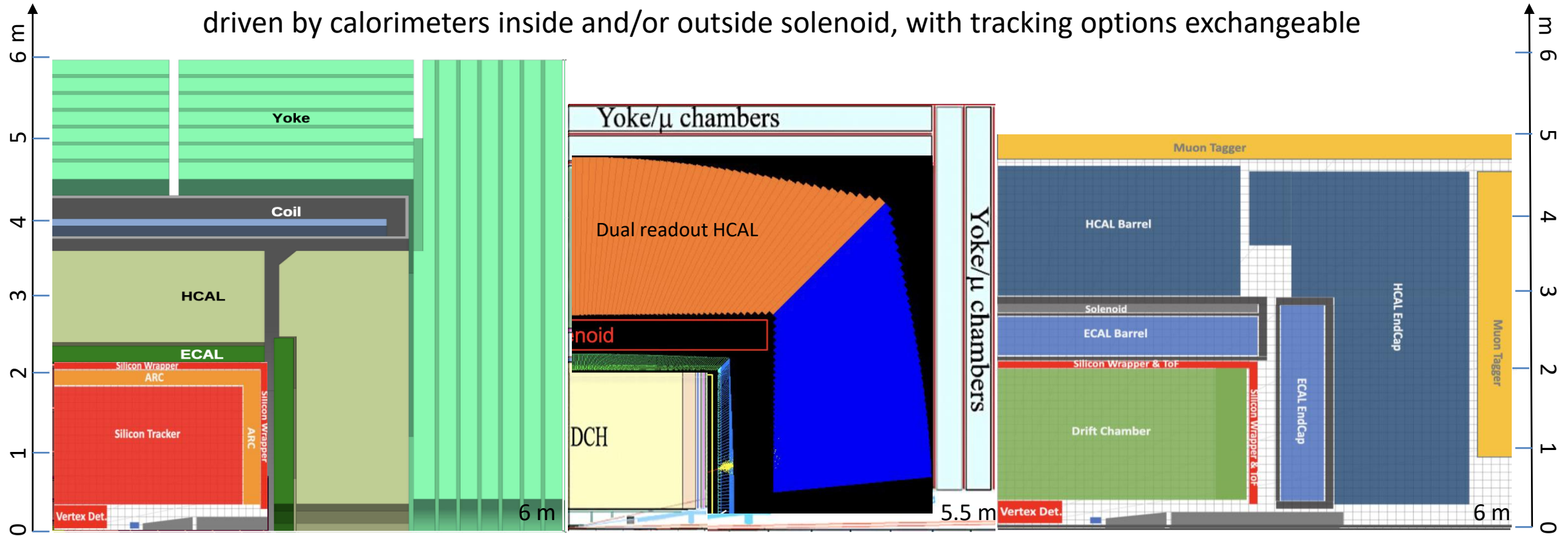
# FCC-ee and CepC at Z-pole are also electroweak and flavor factories

new detector concepts include Particle ID, and high  $\gamma$ -energy resolution

systematics < statistical errors require precision on:  $\sqrt{s}$   $O(10^{-6})$ , lumi.  $O(10^{-4})$ , accep.  $O(10^{-5})$ , B-field  $O(10^{-6})$

Colliders can feature 4 detectors, 3 examples below

driven by calorimeters inside and/or outside solenoid, with tracking options exchangeable



ex. CLD with FST plus  
PID RICH and ToF

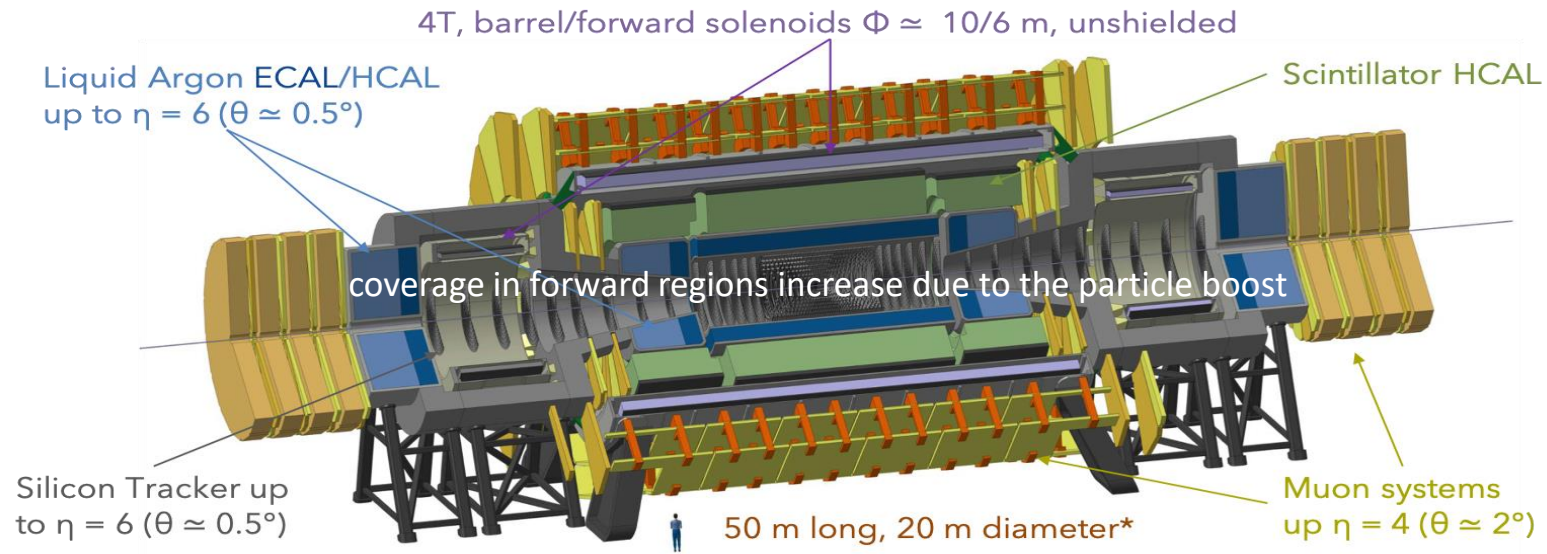
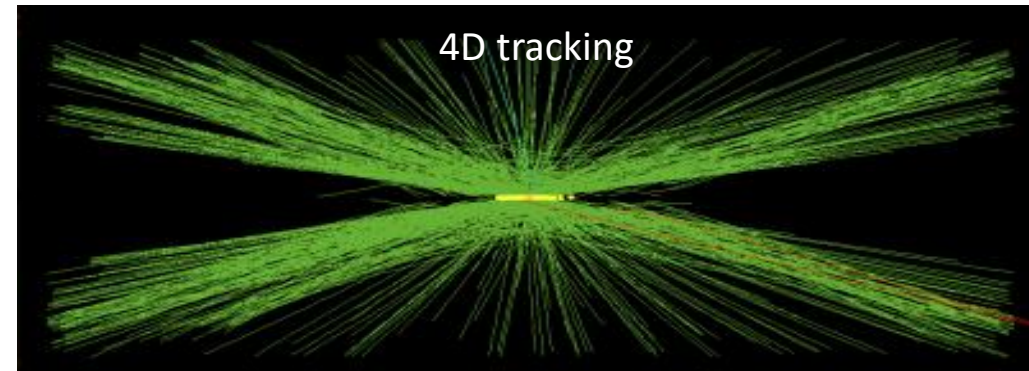
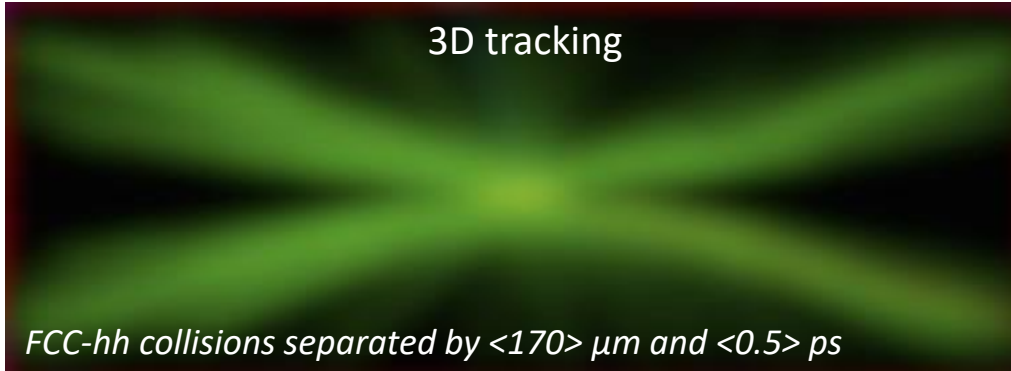
ex. IDEA with DCH PID  
crystal ECAL inside solenoid

ex. Noble Liquid ECAL inside solenoid  
with DCH

# FCC-hh collider detector challenges and concept

collision rate 30 GHz -  $\langle 1000 \rangle$  collisions/BC every 25 ns,  $O(10^2)$  x LHC irradiation

4D measurements with time precision  $O(5)$  ps, on-detector data reduction,  
new data transfer technologies, new material for radiation tolerance



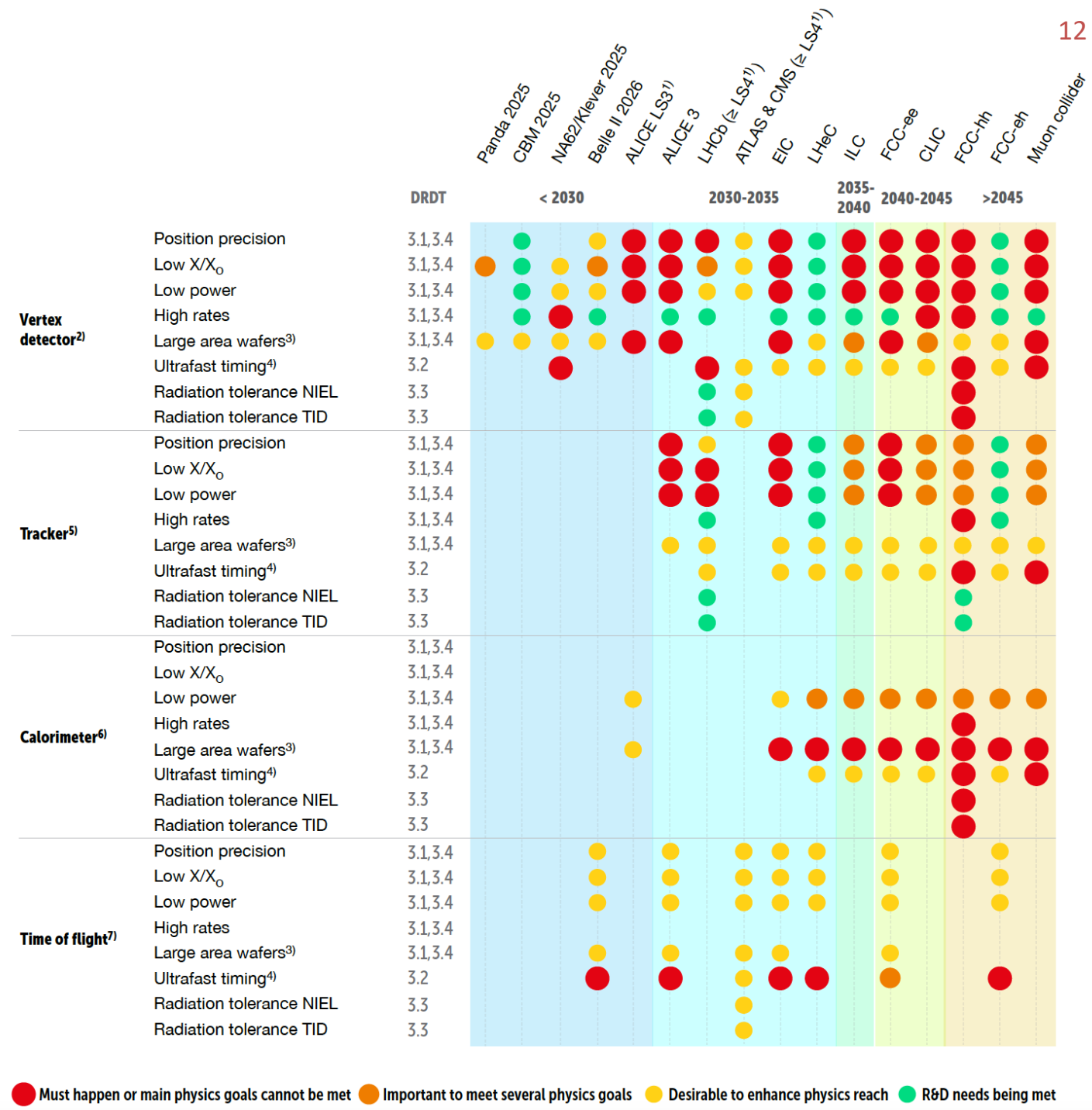


# ECFA R&D roadmap Solid State

Semi-conductor sensors highly granular, fast, transparent and radiation tolerant

Solid state

- DRDT 3.1** Achieve full integration of sensing and microelectronics in monolithic CMOS pixel sensors
- DRDT 3.2** Develop solid state sensors with 4D-capabilities for tracking and calorimetry
- DRDT 3.3** Extend capabilities of solid state sensors to operate at extreme fluences
- DRDT 3.4** Develop full 3D-interconnection technologies for solid state devices in particle physics

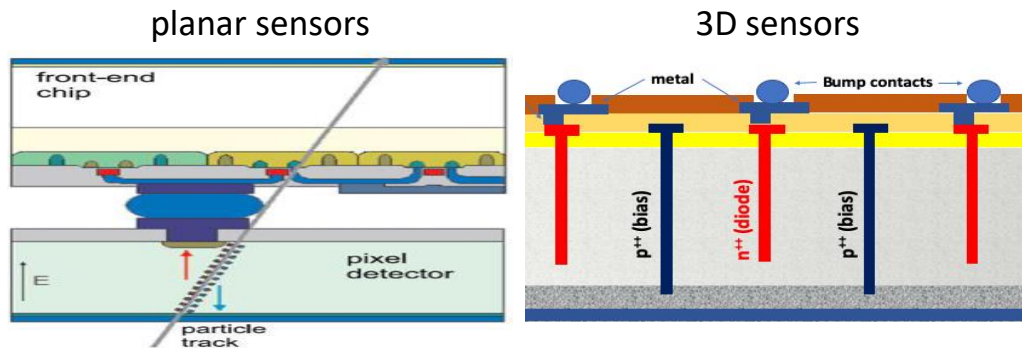


● Must happen or main physics goals cannot be met ● Important to meet several physics goals ● Desirable to enhance physics reach ● R&D needs being met

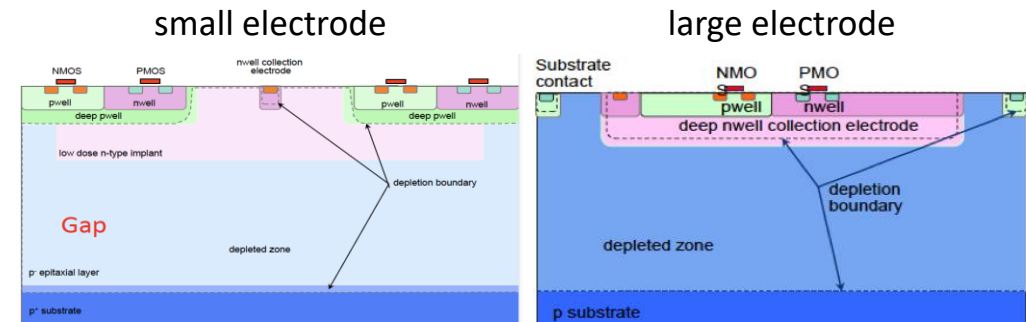
## Two configurations of Si-sensors

### Hybrid design

electronics bumped or wire bonded to Si-sensor  
highest rates & radiation tolerance



Monolithic Active Pixels  
single CMOS imaging process  
thinnest, highest granularity



Several design variants, often driven by process available at the fabrication foundry



# R&D hit resolution, transparency and high rates

## Hybrid design

pixel pitch  $< 50 \mu\text{m}$  at rate capabilities  $O > 1 \text{ GHz/cm}^2$

- Finer granularity (cheaper) connection technology
- 28 nm ASIC technology

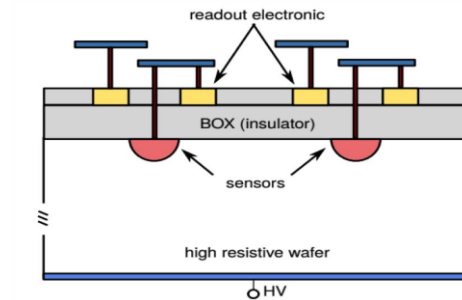
## Monolithic Active Pixels

pixel pitch  $< 20 \mu\text{m}$

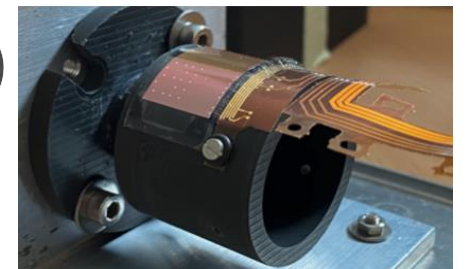
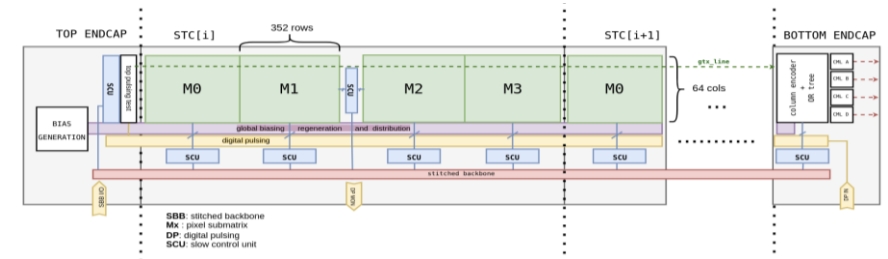
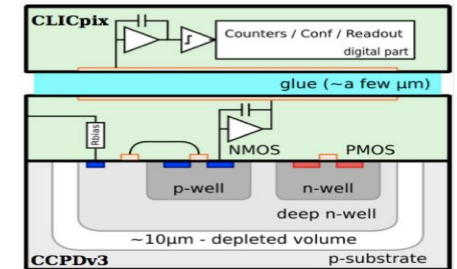
- 65 nm technology pitch
- 12" sensors thinned to  $< 50 \mu\text{m}$
- Low power readout architecture

ex. ALICE ITS3 (LS3)  $10 \times 28 \text{ cm}^2$  sensors, thinned to  $< 50 \mu\text{m}$  for bending,  $\sigma_{\text{hit}} O(3) \mu\text{m}$  at  $X/X_0 O(<0.1)\%$ , power  $O(20) \text{ mW/cm}^2$  for gas flow cooling

Sol technology Through Silicon Via



Conductive glue\*



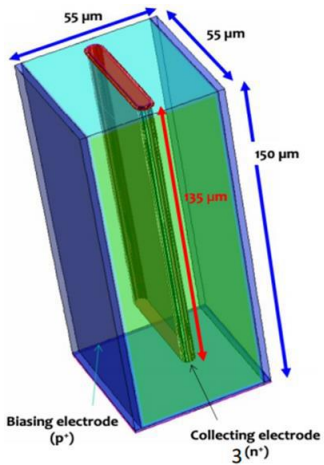
\* Here applied to build a two-tier analog and digital functionality on MAPS design

# R&D high precision timing

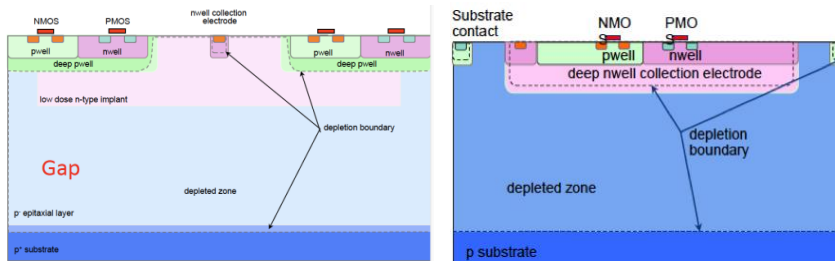
O(10-20) ps for PID layer at FCC-ee and O(5) ps for 4D tracking at FCC-hh

## Designs without gain

Hybrid 3D electrodes  
O(20) ps SoA



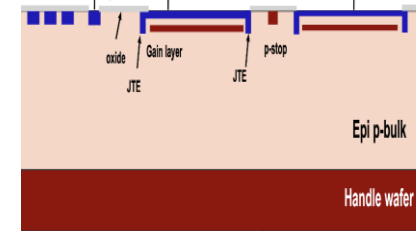
MAPS small/large electrodes  
O(100/50) ps expected



adding low gain amplification

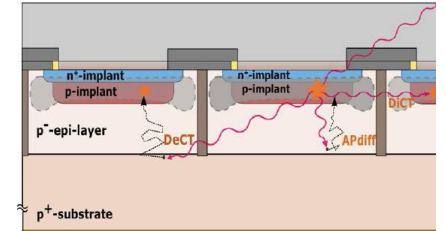
## Designs with gain

Hybrid Low Gain (pad)  
Avalanche Diode O(25) ps SoA



Increase granularity

Single Photon Avalanche Diode  
O(20) ps SoA



Reduce Dark  
Current Rates

- Process tuning for speed and collection efficiency
- New faster process ex. SiGe BICMOS and materials ex. SiC/GaN
- Fast <1 ns risetime and low power electronics

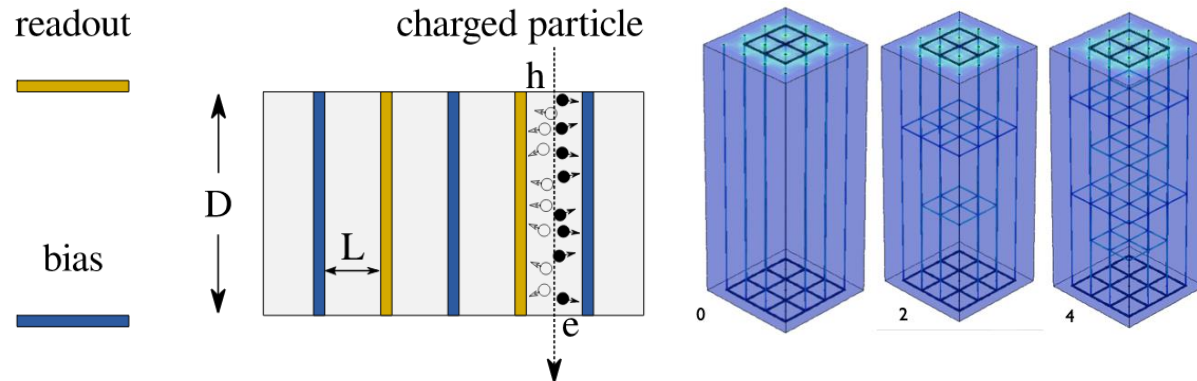
## R&D radiation tolerance

no current technologies would survive below 30 cm at FCC-hh

- Si-sensor sensitive to Non Ionizing Energy Loss, tolerance beyond  $10^{17}/\text{cm}^2$  neq unknown
- ASIC sensitive to Total Integrated Dose, tolerance up to 1 GRad
- For both new materials and 3D process to be evaluated (now of commercial interest)
  - WBG semiconductors Diamond, GaInP, GaAs, GaN, SiC
  - Graphene, Carbon-based metamaterials, nanotubes...

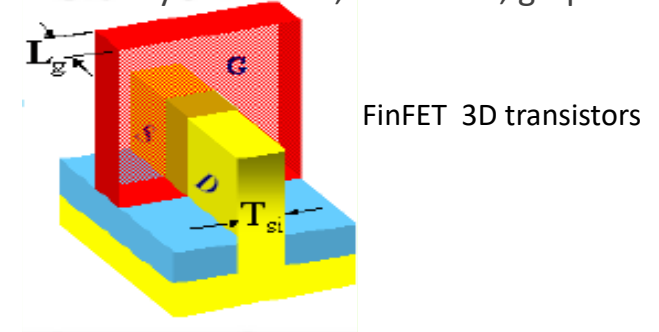
ex. CVD-diamond semiconductor pixel sensors

- 3D design with laser graphitization for thin low  $\rho$  electrodes



ex. ASICs

- Higher dielectric thick oxide (multiple) gates
- Carbon based beyond CMOS, nanotube, graphene





# ECFA R&D roadmap Particle ID and photon

Ring Imaging Cherenkov, Time of Flight, Sensitive materials and photosensors

PID and Photon

- DRDT 4.1** Enhance the timing resolution and spectral range of photon detectors
- DRDT 4.2** Develop photosensors for extreme environments
- DRDT 4.3** Develop RICH and imaging detectors with low mass and high resolution timing
- DRDT 4.4** Develop compact high performance time-of-flight detectors

SPS fixed target  
FAIR (nep)  
PIP-II/LBNF/DUNE  
Dark matter, noble liquids  
ALICE 3  
LHCb ( $\geq$ LS4)  
ATLAS/CMS ( $\geq$ LS4)  
EIC  
LHeC  
Belle II Upgrade  
ILC  
FCC-ee  
CLIC  
FCC-hh  
FCC-eh  
Muon collider

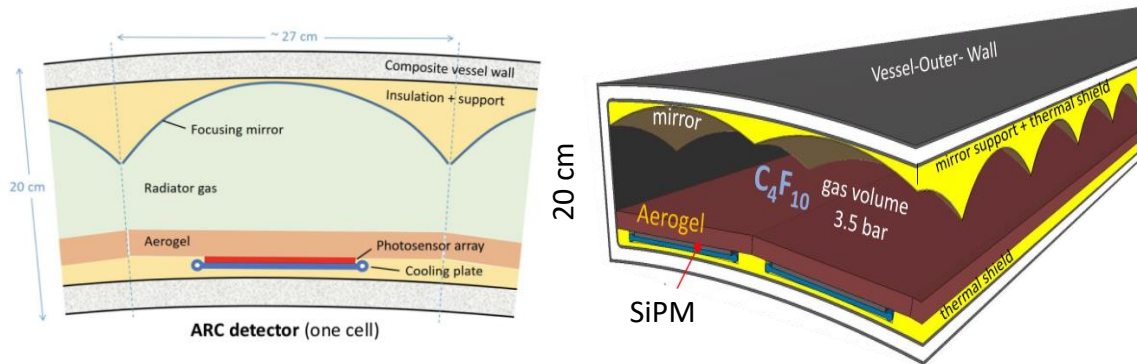
		DRDT	< 2030	2030-2035	2035-2040	2040-2045	>2045
<b>RICH and DIRC technologies</b>	Rad-hard	4.2	● ●	● ● ● ●	● ● ● ●	● ● ● ●	
	Rate capability	4.2	● ●	● ● ● ●	● ● ● ●	● ● ● ●	
	Fast timing	4.3	● ●	● ● ● ●	● ● ● ●	● ● ● ●	
	Spectral range and PDE	4.1	● ●	● ● ● ●	● ● ● ●	● ● ● ●	
	Radiator materials	4.3	● ●	● ● ● ●	● ● ● ●	● ● ● ●	
	Compactness, low $X_0$	4.3	● ●	● ● ● ●	● ● ● ●	● ● ● ●	
<b>Time of flight</b>	Rad-hard	4.2	● ●	● ● ● ●	● ● ● ●	● ● ● ●	
	Low X	4.3	● ●	● ● ● ●	● ● ● ●	● ● ● ●	
	Fast timing to <10ps level & clock distribution	4.3	● ● ●	● ● ● ●	● ● ● ●	● ● ● ●	
<b>Other</b>	TRD	4.3	● ●	● ● ● ●	● ● ● ●	● ● ● ●	
	dE/dx	4.3	● ● ●	● ● ● ●	● ● ● ●	● ● ● ●	
	Scintillating fibres (light yield, rad-hard & timing)	-		● ● ● ●	● ● ● ●	● ● ● ●	
<b>Silicon photomultipliers</b>	Rad-hard	4.2	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	Low noise	4.1	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	Fast timing	4.1	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	Radio purity	4.2	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	VUV / cryogenic det op	4.2	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
<b>Vacuum photon detectors</b>	Photocathode ageing & rate capability	4.2	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	Fast timing	4.1	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	Fine granularity / large area	4.1	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	Spectral range and PDE	4.1	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	Magnetic field immunity	4.2	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
<b>Gaseous photon detectors</b>	Photocathode ageing & rate capability	4.2	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	Fine granularity / large area	4.1	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●
	Spectral range, PDE and fast timing	4.1	● ●	● ● ● ●	● ● ● ●	● ● ● ●	● ● ● ●

● Must happen or main physics goals cannot be met ● Important to meet several physics goals ● Desirable to enhance physics reach ● R&D needs being met

# R&D Particle Identification with RICH

Challenge to reach  $\gtrsim 3\sigma$   $\pi/K$  separation up to  $O(50)$  GeV

new concept ex. Thin Array of RICH Cells ( $X/X_0 < 10\%$ ) for FCC-ee  
coupling aerogel and gas radiator with single SiPMs readout

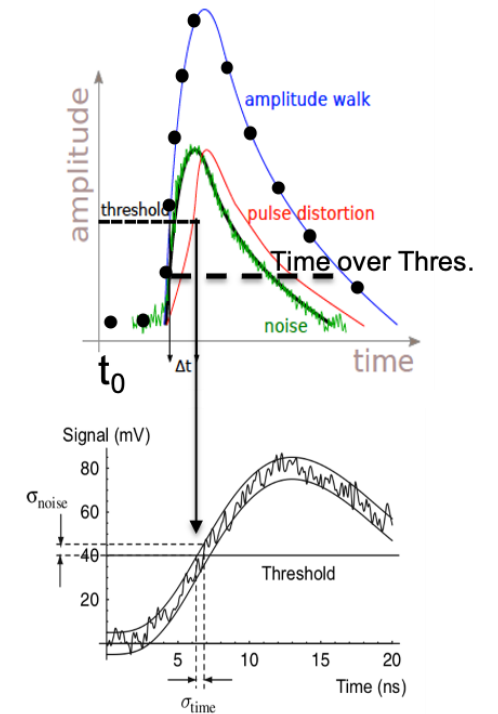


- New materials for tunable refractive index
- Improved optics ex. lens, mirror coating

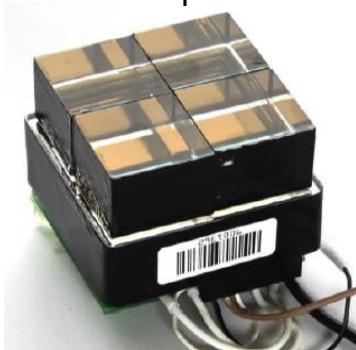
# R&D Time of Flight precision

SoA is at  $O(20)$  ps target for FCC-ee  $O(10)$  ps for PID, and  $\lesssim 5$ ps at FCC-hh

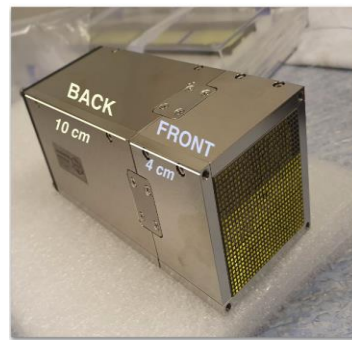
- Pulse fluctuations and electronics jitter are the limitation
  - increased speed and S/N
- Resolution also depends on number of measurements
  - hits in tracking, photons in RICH, showers particles in calorimeters, single Time of Amplitude at threshold or Waveform Sampling\*



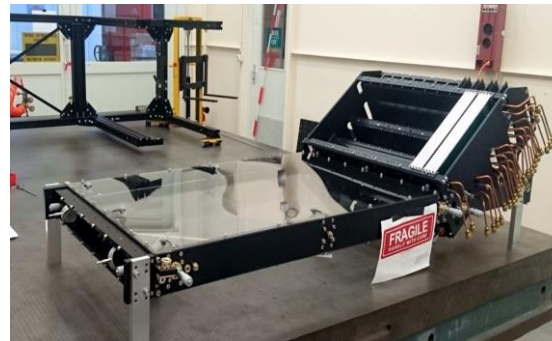
ALICE  
Fast Interaction Trigger  
Cherenkov radiator  
+ MCP-PMT  
 $\approx 30$  ps



LHCb  
Spaghetti Calo.  
crystal/scint. + MCP PMT  
waveform sampling  
 $\approx 20$  ps



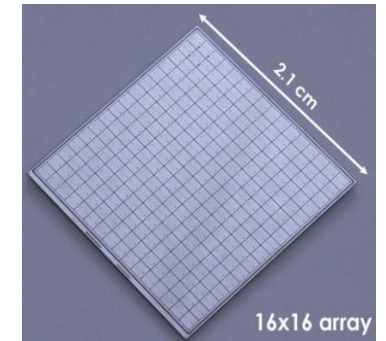
LHCb  
TORCH RICH  
Cerenkov radiator  
+ MCP-PMT  
SPTR  $\approx 70$  ps



CMS  
Timing Layer (pile-up)  
LYSO crystal + 2 SiPM  
ToA and ToT  
 $\approx 20$  ps



ATLAS - CMS  
Timing Layer  
LGAD Si-sensors  
ToA and ToT  
 $\approx 25$  ps



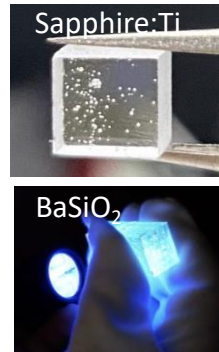
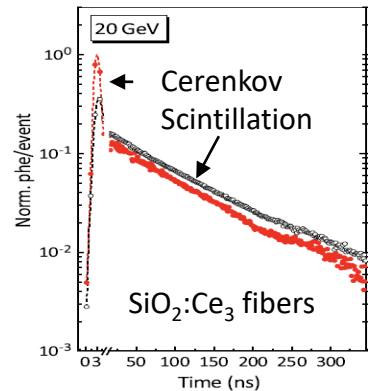
\* Time-walk correction can be provided by ToT, waveform sampling or ADC amplitude depending on system



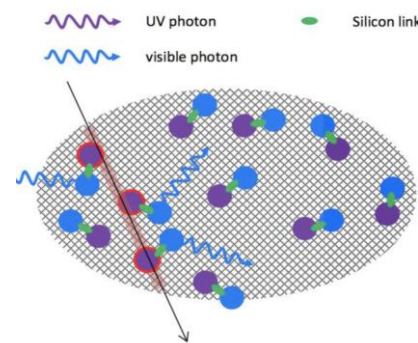
# R&D Scintillator and Cherenkov materials

- ex. new crystals (fibers) providing both Cherenkov and scintillating light (doping)
- ex. new nano-materials, luminophore WLS, quantum dots tuning of WL with size
- 3D printing for unconventional shapes, ex. square fibers for Dual Readout calorimeters

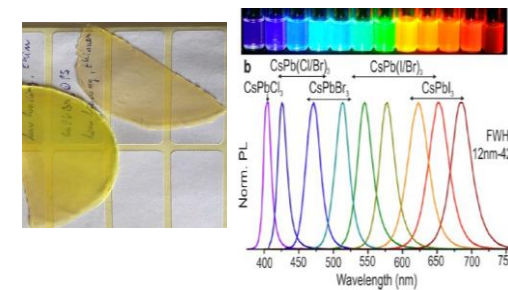
Separate sources  
with waveform sampling



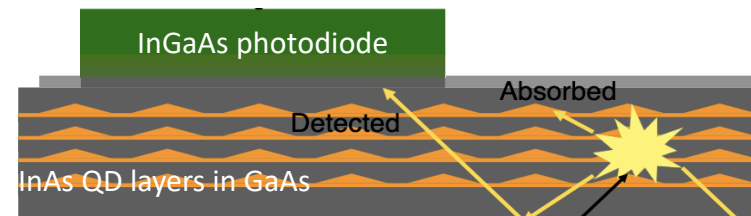
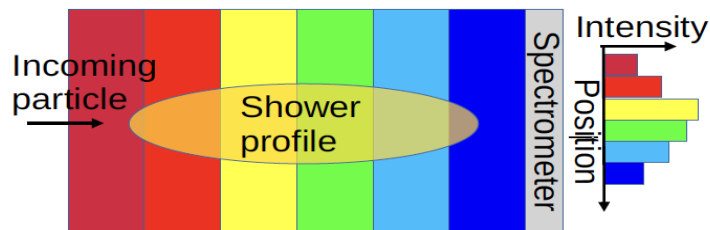
luminophore



Quantum Dot ex. perovskite  
embedded in polymer



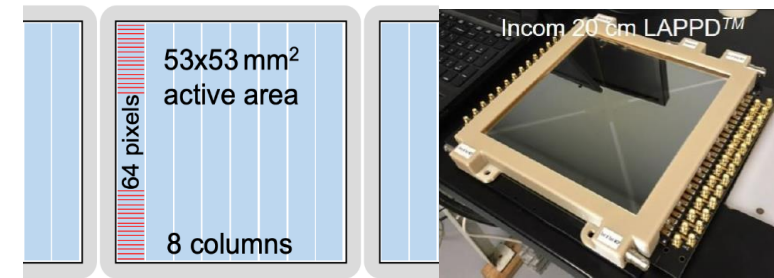
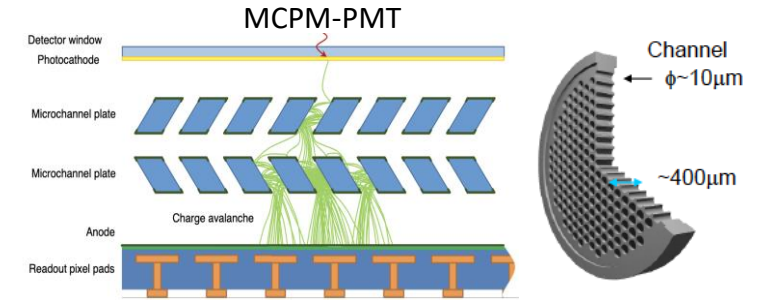
Quantum Dots could allow new cutting edge concepts for depth segmentation in homogenous calorimetry (left)  
and 4D scintillating tracking in monolithic scintillating photodiode sensors (right)



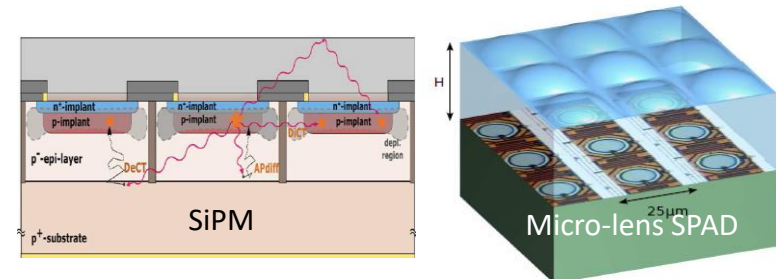
# R&D Photosensors

- MCP-PMT

- ex. Large Area Picosecond PhotoDetectors ( $20 \text{ cm}^2$ ),  $O(1) \text{ mm}^2$ , SPTR  $O(30) \text{ ps}$ 
  - Improved photocathode efficiency for radiation tolerance
  - Hybrid design with pixel ASIC integration in vacuum tube
  - Nanopore channels for ultra high granularity
  - Design for MIP (with Cerenkov Radiator or from secondary emission)



- SiPM hybrid analog design,  $1(3 \times 3) \text{ mm}^2$ ,  $30(80) \text{ ps}$
- SPAD monolithic digital pixel counting,  $50 \mu\text{m}$  pitch, SPTR  $O(20) \text{ ps}$ 
  - Reduce Dark Current Rates (new materials ex. WBG GaInP, GaAs, SiC, GaN)
  - Improve QE, particularly in UV and NIR
  - Micro-lens array design to compensate fill factor
  - Lower pitch

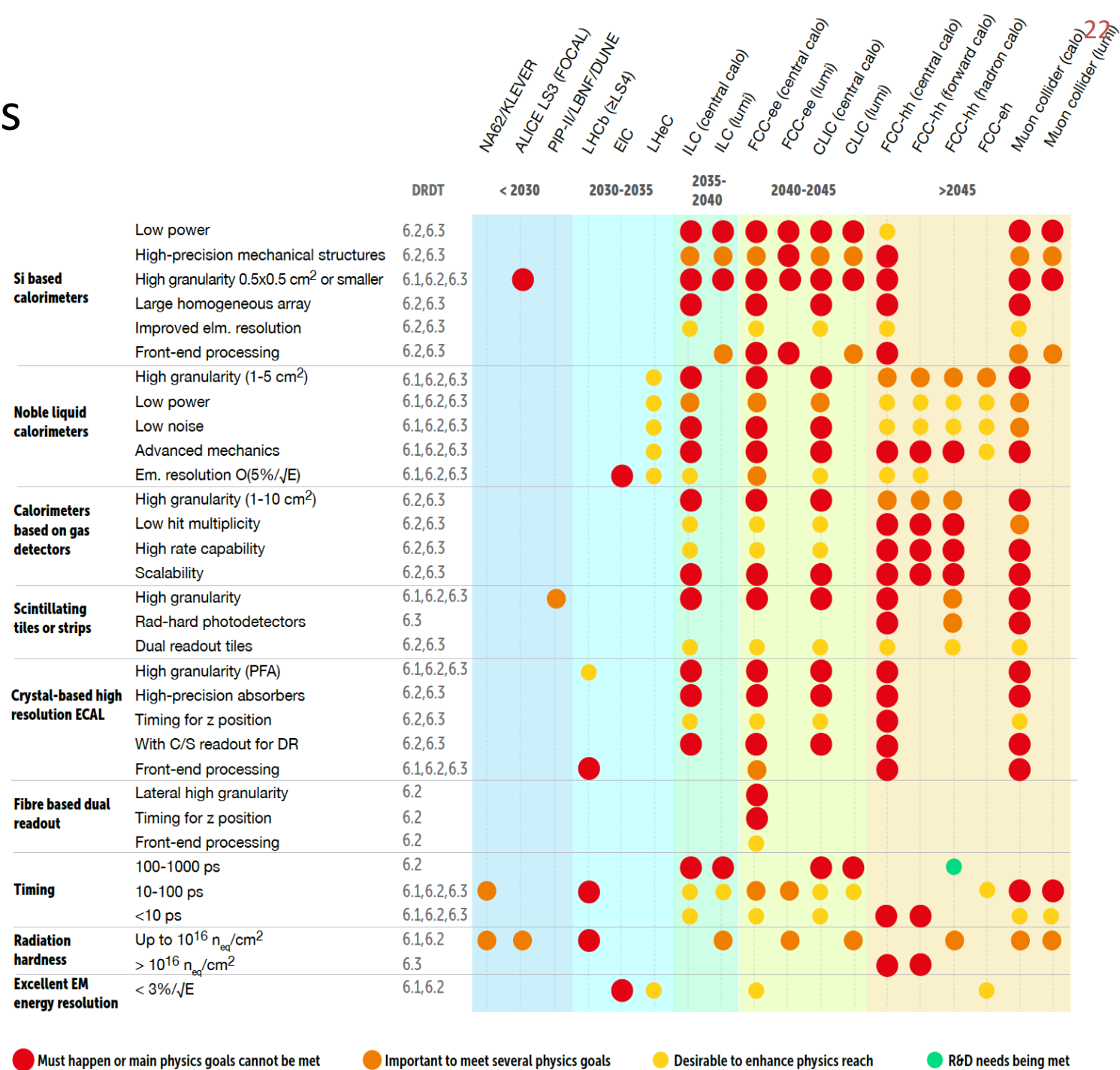


# ECFA R&D roadmap Calorimeters

Several concepts with specific performance  
several sensor technology options

## Calorimetry

- DRDT 6.1** Develop radiation-hard calorimeters with enhanced electromagnetic energy and timing resolution
- DRDT 6.2** Develop high-granular calorimeters with multi-dimensional readout for optimised use of particle flow methods
- DRDT 6.3** Develop calorimeters for extreme radiation, rate and pile-up environments





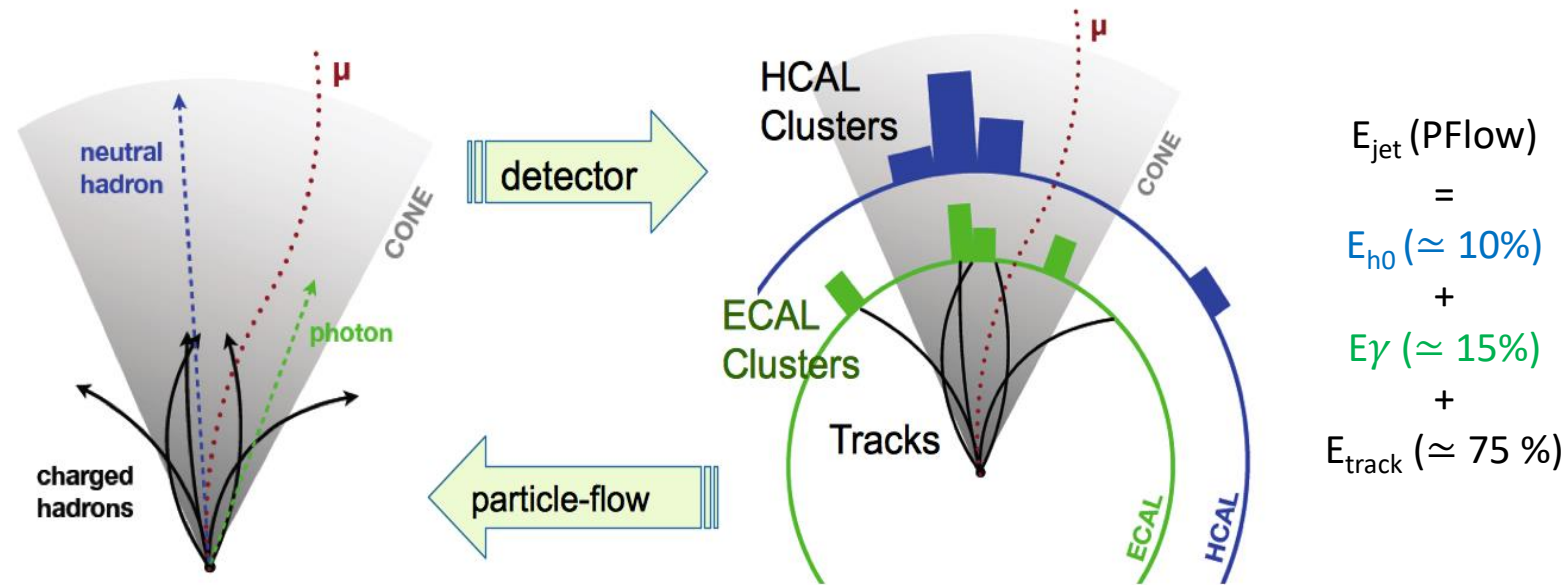
# Calorimeter concepts

e- $\gamma$  electromagnetic showers develop in front segment

hadronic interaction develop deeper in back segment

homogenous calorimeters provide best e- $\gamma$   $\sigma(E)/\sqrt{E}$  O(3)%

so far only sampling calorimeters for hadrons, current target is  $\sigma(E_{\text{Jet}})$  O(30)%/ $\sqrt{E}$



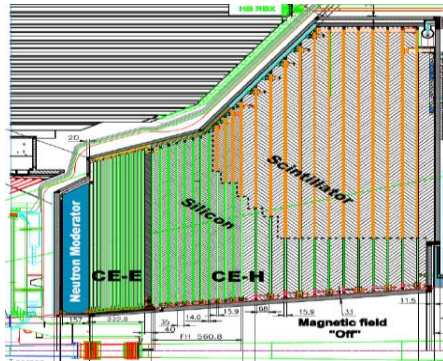
High transverse granularity for charged track shower association (PFlow technique)

Hadron shower energy compensation (calibration) with “dual readout” measuring both em and had. shower components or from depth segmentation providing the shower shape

# Calorimeter configurations

Sampling  
absorber (W/Pb/Cu/Fe/Brass)  
Solid State, Scint. tiles, fibers, Gas, Noble Liquid

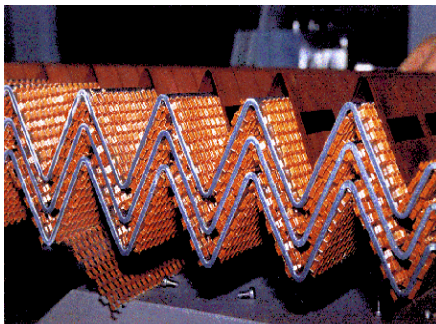
High Granularity  
Si-pads and scint tiles/MPGDs



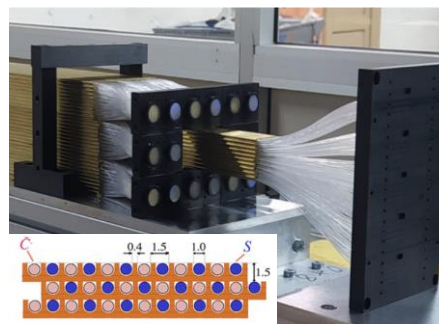
Shashlik EM concept  
Scintillator + WLS



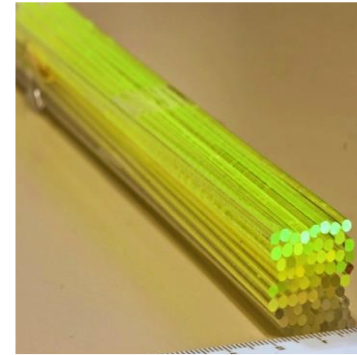
Noble Liquid (LAr)



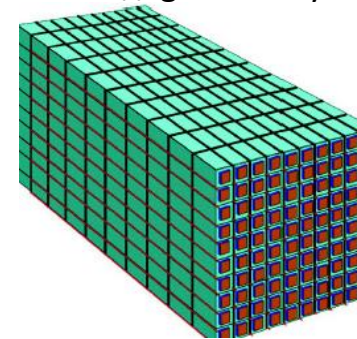
Spaghetti Dual Readout  
Scint. & Cherenkov fibers



ECAL  
crystal fibers

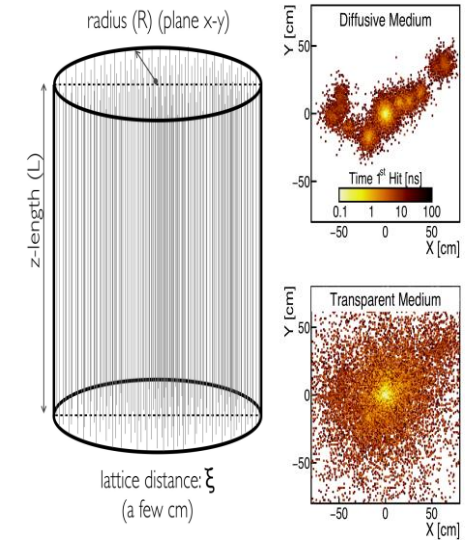


HCAL with  
 $\perp$  &  $\parallel$  granularity



Homogenous  
new concepts

Opaque scintillator  
crystal grains



## R&D different concepts

sensitive elements and photosensors R&D are covered in other technology areas

- High Granularity Calorimeter
  - Improved sampling fraction for e- $\gamma$  energy, ex monolithic Si-sensors w/ low power electronics
  - Ultimate pixel digital counting with <10 ps for full 5D shower profiles
- Dual Readout calorimeter
  - Single dual readout fibers providing both scintillating and Cherenkov light
  - Waveform sampling for shower ToF (depth in calorimeter)
- Noble Liquid Calorimeter
  - Improve transverse and depth segmentation with large size multiple layer PCBs
  - Light cryostat vessel, cold electronics, high density feedthrough\*
- Homogenous calorimeters
  - Implement dual readout, ex. wavelength filtering w/ two photosensors, waveform sampling or physical depth segmentation

\* common problematics NL TPCs and magnets



# ECFA R&D roadmap Gaseous detectors

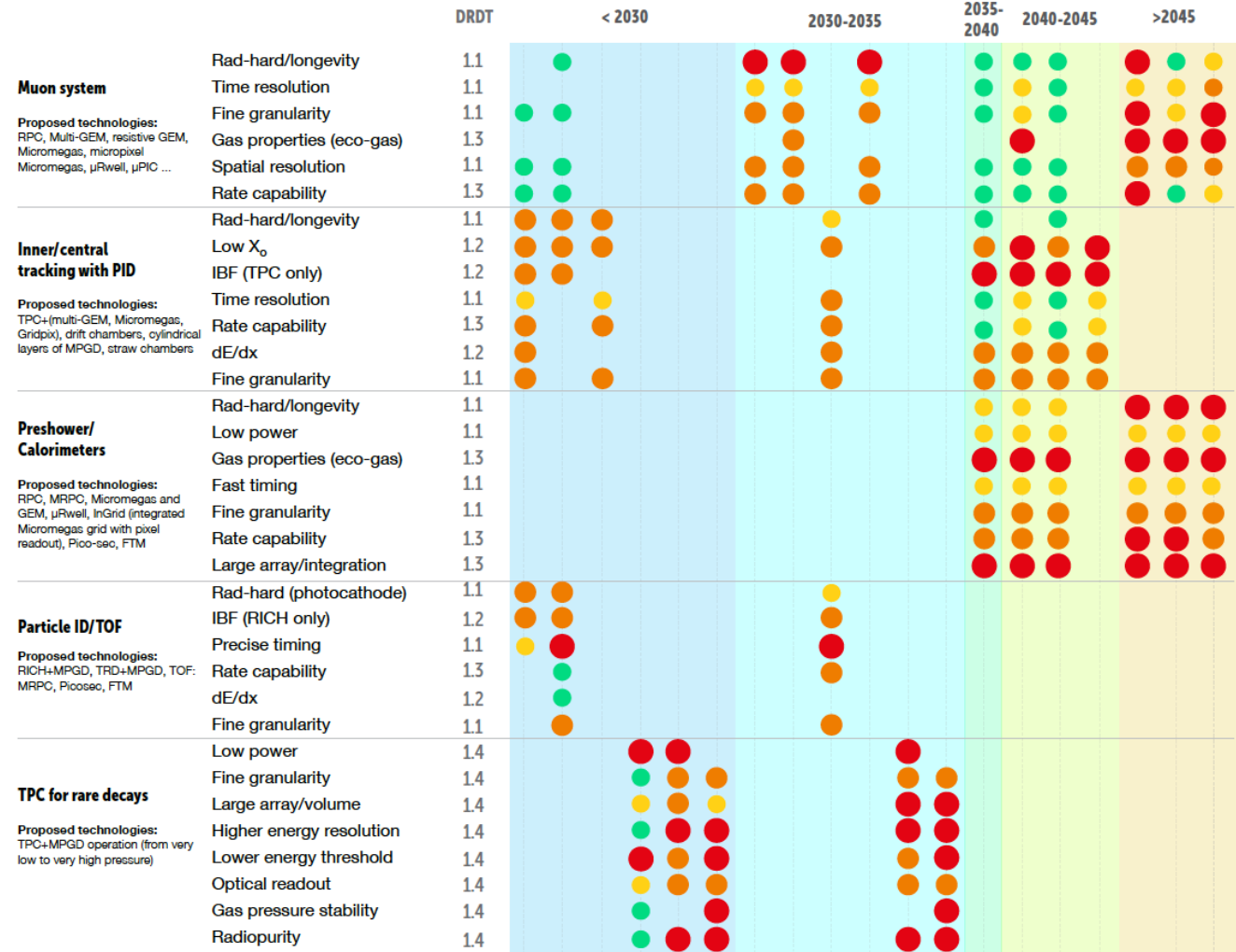
Versatile (cheap) systems in large areas

wide range of application as sensitive and/or readout elements

## Gaseous

- DRDT 1.1** Improve time and spatial resolution for gaseous detectors with long-term stability
- DRDT 1.2** Achieve tracking in gaseous detectors with dE/dx and dN/dx capability in large volumes with very low material budget and different read-out schemes
- DRDT 1.3** Develop environmentally friendly gaseous detectors for very large areas with high-rate capability
- DRDT 1.4** Achieve high sensitivity in both low and high-pressure TPCs

SPS fixed target (Amber, NA62+, NA60)  
 FAIR (PANDA, CBM)  
 Other fixed target  
 Neutrino near detectors (COMET, MU2E,...)  
 Large ton dual-phase<sup>1)</sup>  
 Light dark matter...<sup>2)</sup>  
 LHCb (eLS4)  
 ATLAS/CMS (eLS4)  
 EIC  
 LHeC  
 R&D DM/Neutrino experiments<sup>3)</sup>  
 R&D ton scale 0nbb  
 ILC  
 FCC-ee  
 CLIC  
 STCF  
 FCC-hh  
 FCC-eh  
 Muon collider



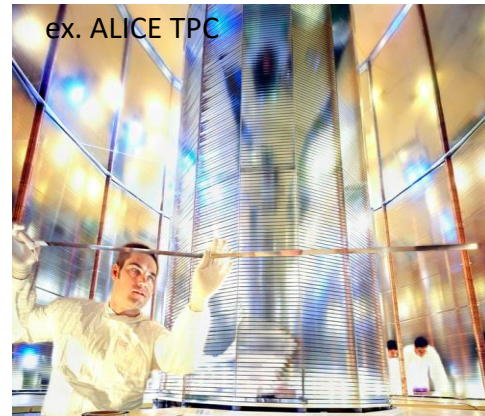
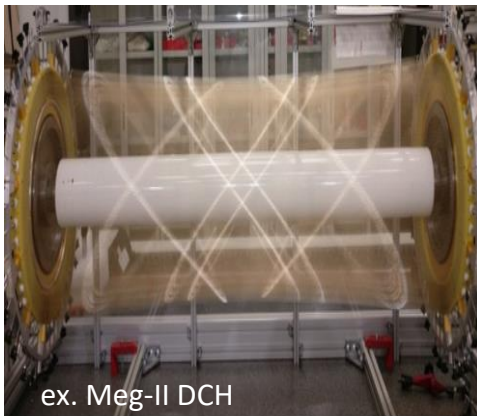
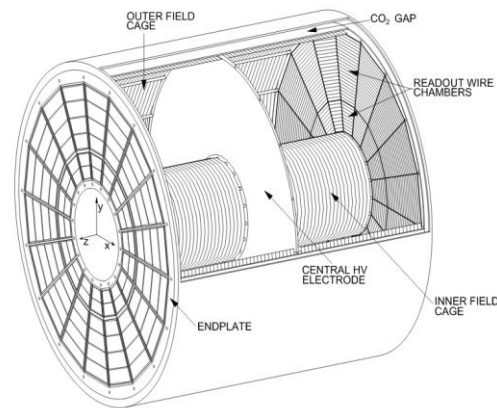
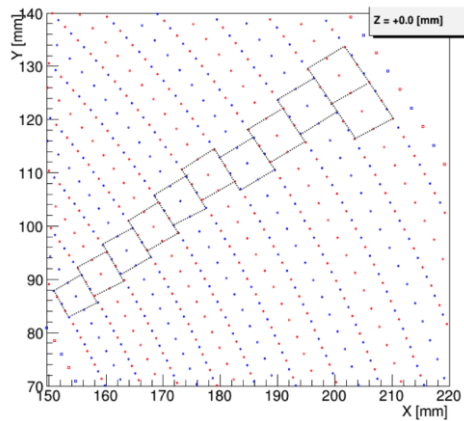
● Must happen or main physics goals cannot be met    ● Important to meet several physics goals    ● Desirable to enhance physics reach    ● R&D needs being met

# Central Tracking and Particle IDentification with DCH or TPC

enabling at the same time best momentum resolution and PID up to 50 GeV for FCC-ee

## Central Tracking

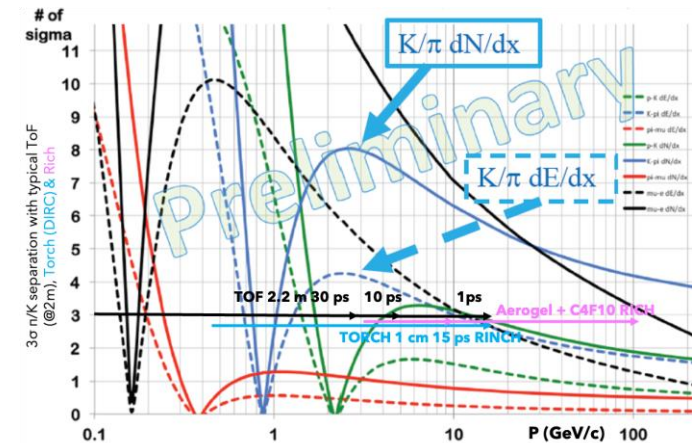
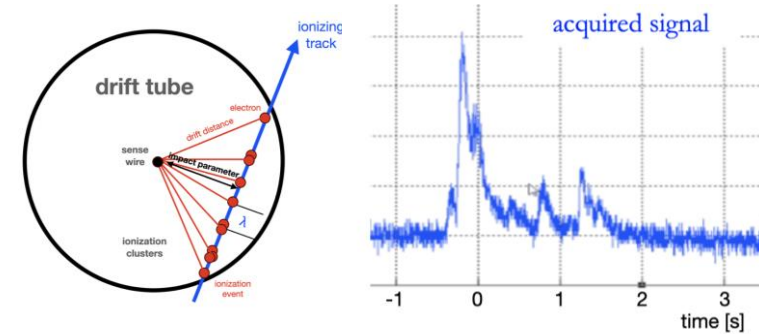
$O(100)$  points with  $O(100)$   $\mu\text{m}$  precision  
 $O(1/5)$  %  $X/X_0$  barrel/endcap



## PID

new concept of waveform sampling  $O(1)$  GHz\*  
 to count e-clusters for  $O(<3\%)$  energy resolution

ex. FCC-ee IDEA DCH



10 – 20 ps ToF to cover  $dE/dx$  crossing

\* also expected to improve position resolution from 100  $\mu\text{m}$  to  $\lesssim 80$   $\mu\text{m}$

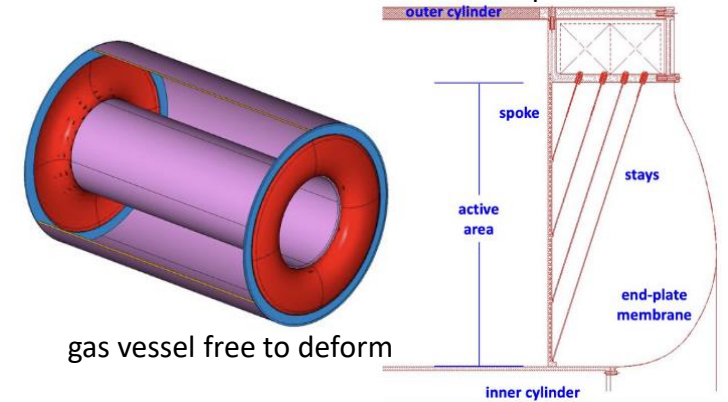
# R&D Drift Chamber and Time Projection Chamber

## DCH mostly engineering

- Large size design structure and production
- Light and thin wires ex. 40  $\mu\text{m}$  Al/C/Ti (field), 20  $\mu\text{m}$  Mo/W (sense)
- $dN/dx$  measured through waveform sampling electronics  $O(1)$  GHz

ex. FCC-ee IDEA DCH

DCH wire tension compensation

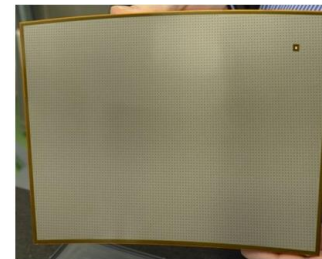


ex. MPGD readout ILD TPC

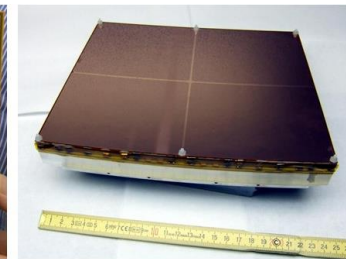
## TPC main challenge to reduce ion backflow

- Operating conditions (gas, voltages, pressure)
- Highly sensitive and granular readout MPGD
  - $dN/dx$  measured through cluster counting

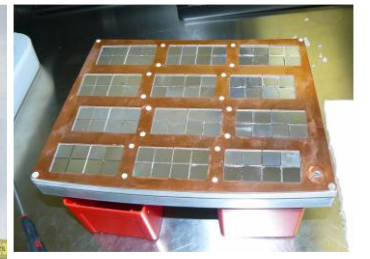
Micromegas



GEM



Gridpix



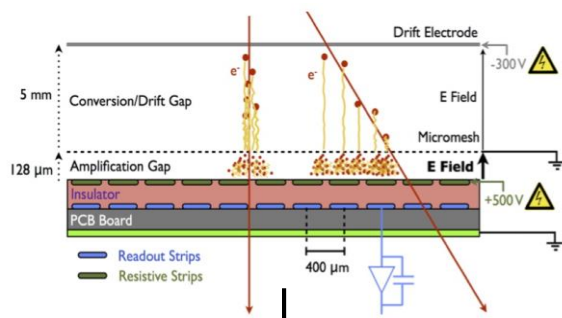


# MicroPattern Gas Detectors

precision down to  $O(50) \mu\text{m}$  at rates  $O(1) \text{ MHz/cm}^2$

Muon chambers, calorimeter preshower or hadronic segment, readout system elements

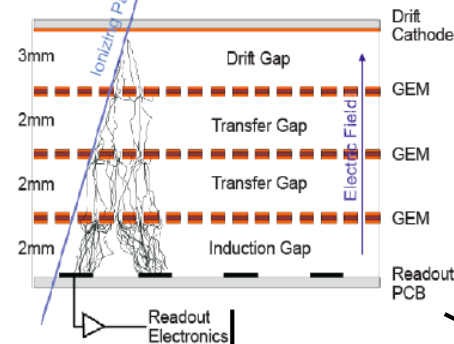
MicroMegas (MM)



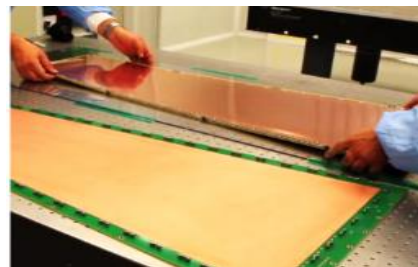
ATLAS new small wheels



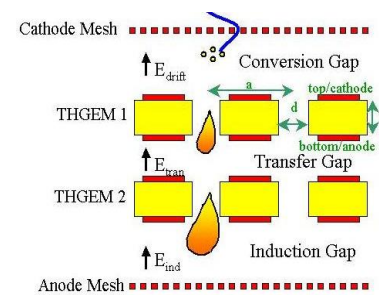
GEM



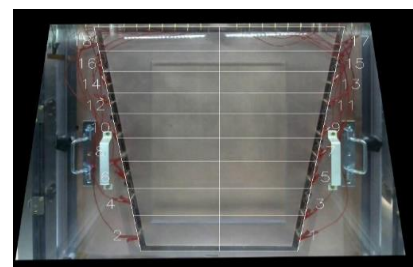
CMS



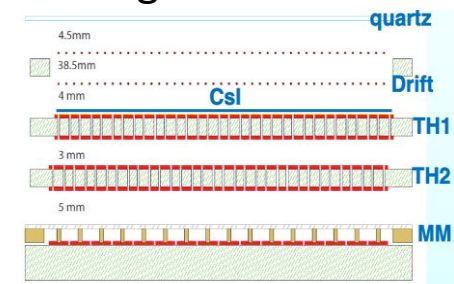
THGEM



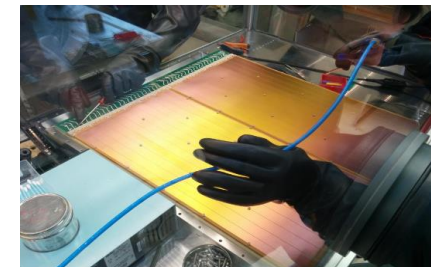
ALICE TPC



Hybrid design THGEM + MM



COMPASS RICH

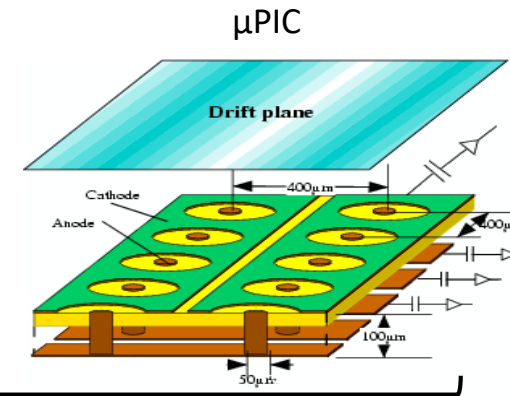
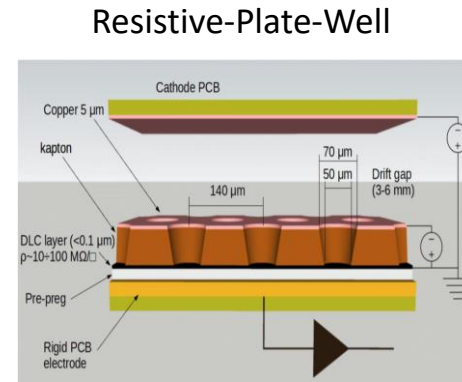
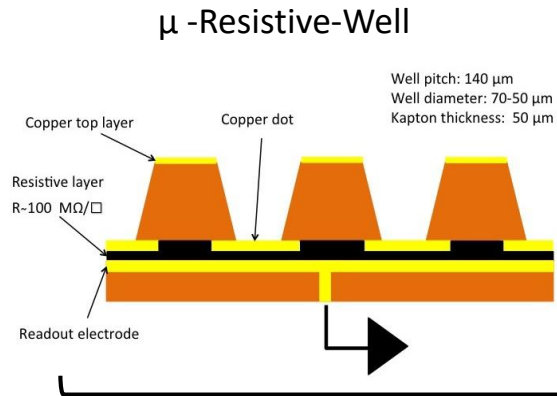


ex. muon tracking systems

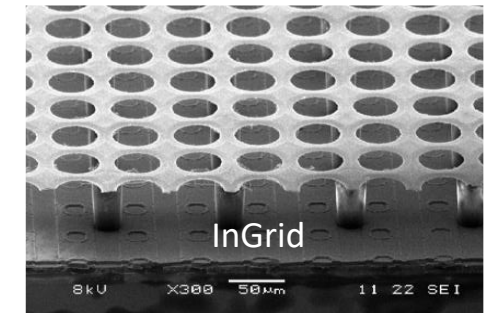
ex. readout systems ionization (left) light (right)

# R&D MicroPattern Gas Detectors precision and rates

approach performance of Solid State in printed board technology or CMOS monolithic designs



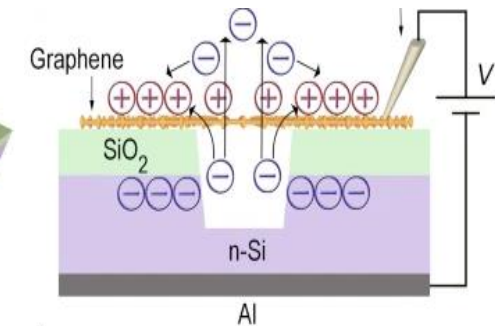
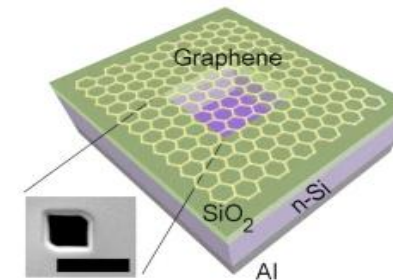
CMOS MicroMegas  
mesh grown on pixel ASIC



New GEM-like single amplification stage with fine pitch strips (left) or pixels (right)

Monolithic design

- Improve rate capability  $O(\geq 100)$  MHz/cm<sup>2</sup>
  - AC coupling through DLC coating resistive layer
- 3D printing, dry plasma ink jet printing
  - developed for flexible PCB devices
- New material concept ex. Graphene grid

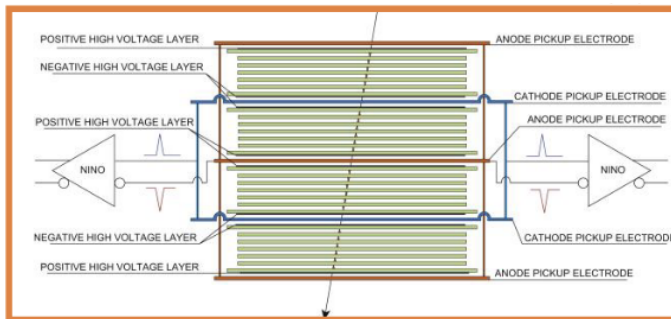


## R&D timing precision

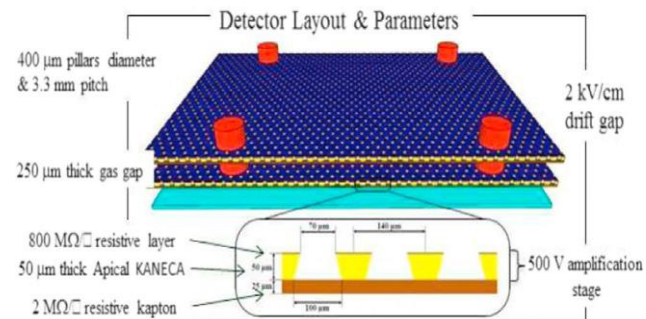
- Multigap RPCs
  - low  $\rho$  material and thin gaps  $O(100)$   $\mu\text{m}$
- Fast Timing MPGD
  - Thin gaps multiple GEM amplification stages on top of  $\mu$ -rwell
- MicroMegas with Cherenkov radiator and photocathode
  - Improve photocathode QE and radiation tolerance
    - New materials ex. hydrogenated diamond spray, nano-diamond (gold) grains (UV-sensitive)

Multigap RPCs

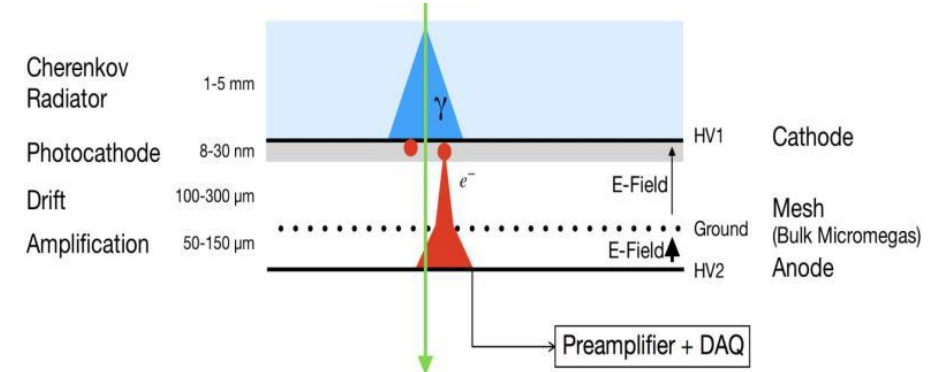
24 x 160  $\mu\text{m}$  gaps  $O(20)$  ps



Fast Timing MPGD



Picosec MM (1 MIP  $\approx$  10 pe)  $O(25)$  ps





## R&D Eco-friendly gas mixtures

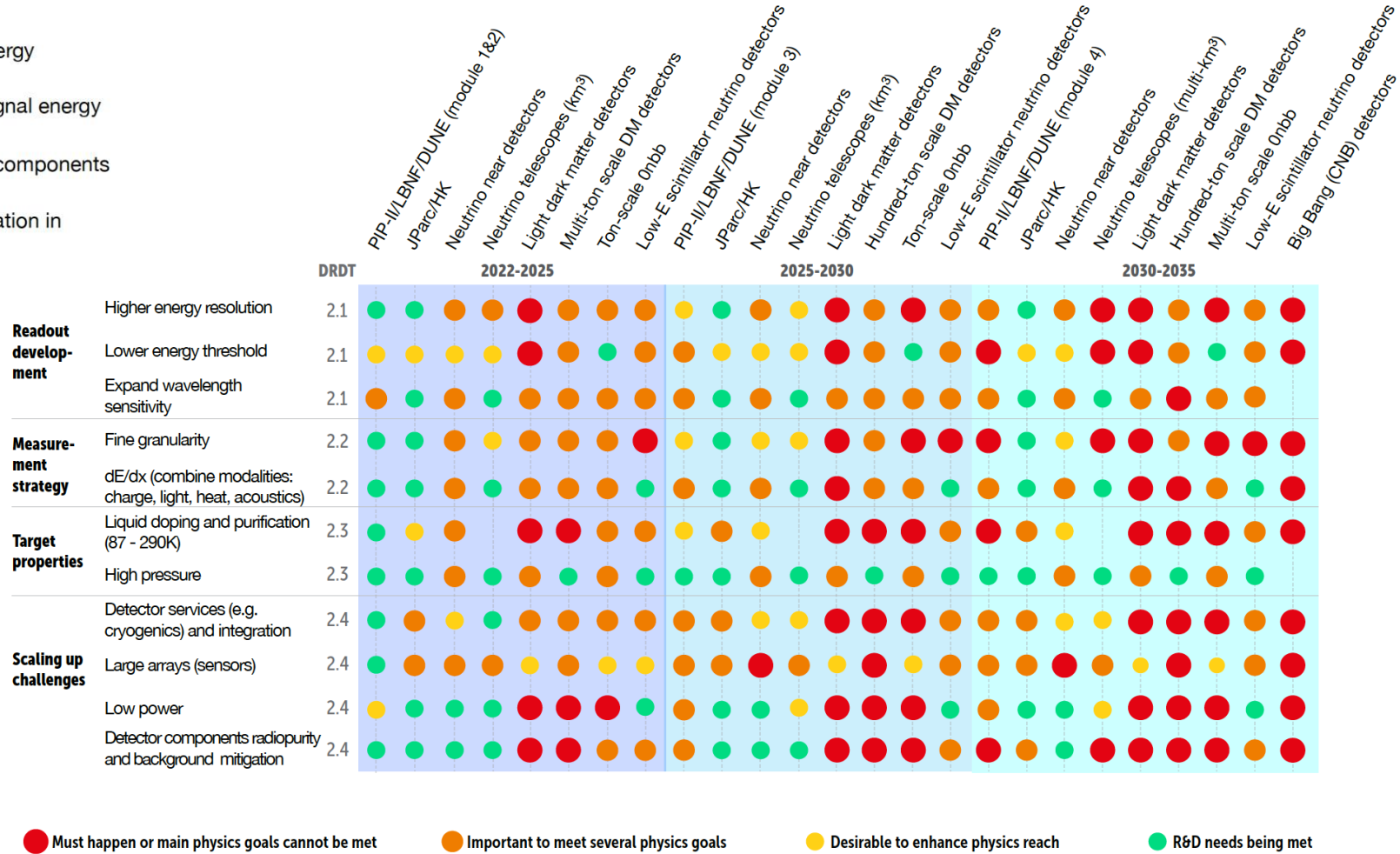
- Reduced discharge of currently used GHG ( $C_2H_2F_4$ ,  $CF_4$ ,  $SF_6$ ,  $C_4F_{10}$ )
  - Recirculation/recuperation/abatement should fulfil current regulation
- Alternative mixtures
  - HydroFluoroOlefin (ex.  $C_3H_2F_4$ ) commercial refrigerant replacements
    - do not yet provide full performance without some (relatively small) fraction of  $CF_4$
  - New design and operation conditions to compensate possible performance loss

# ECFA roadmap Liquid detectors

## Water Cerenkov, Noble Liquid, Liquid Scintillator

Liquid

- DRDT 2.1** Develop readout technology to increase spatial and energy resolution for liquid detectors
- DRDT 2.2** Advance noise reduction in liquid detectors to lower signal energy thresholds
- DRDT 2.3** Improve the material properties of target and detector components in liquid detectors
- DRDT 2.4** Realise liquid detector technologies scalable for integration in large systems



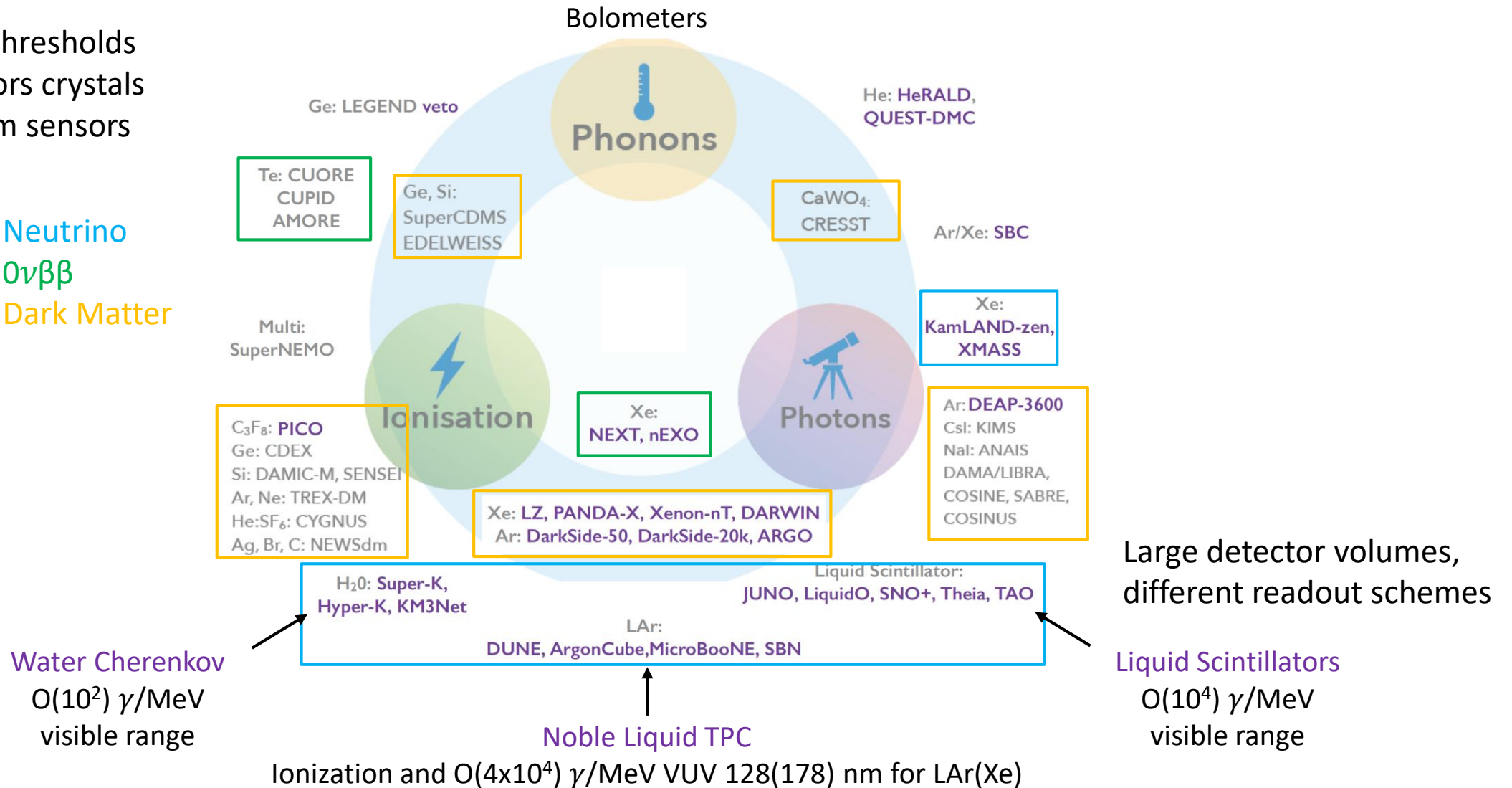
# Neutrino, Dark Matter, $0\nu\beta\beta$ decay detectors

Strategy driven by energy sensitivity

goal to measure the different signals in same multi-purpose detectors of increasing volumes

Low energy thresholds  
small detectors crystals  
with quantum sensors

Neutrino  
 $0\nu\beta\beta$   
Dark Matter



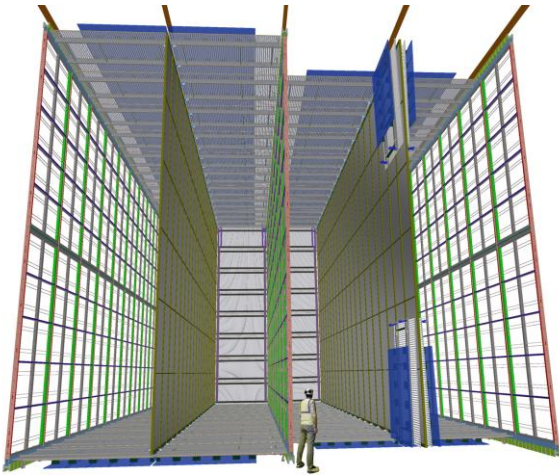


# Noble liquid TPC Neutrino

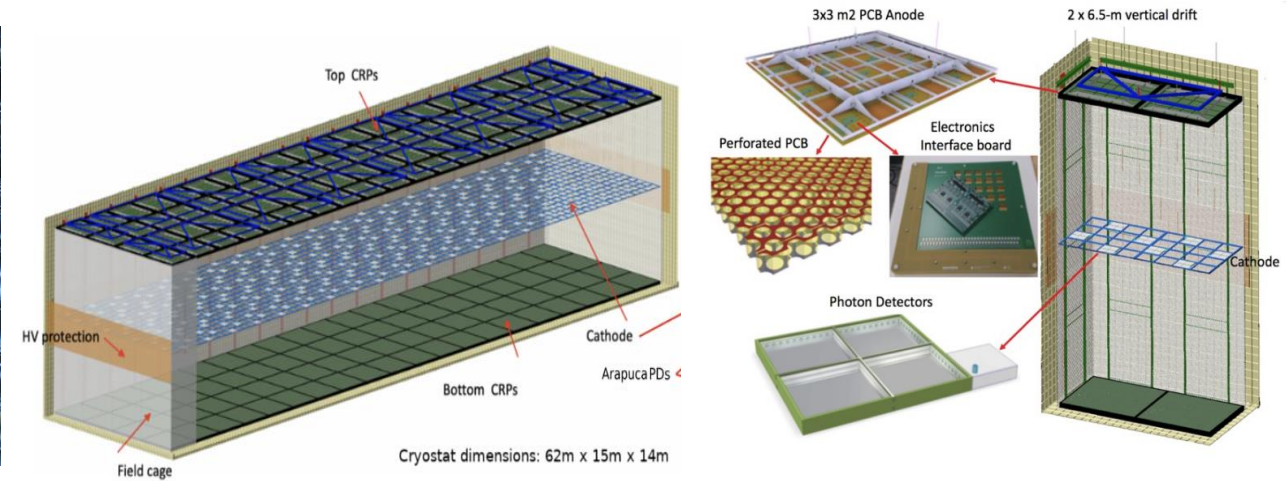
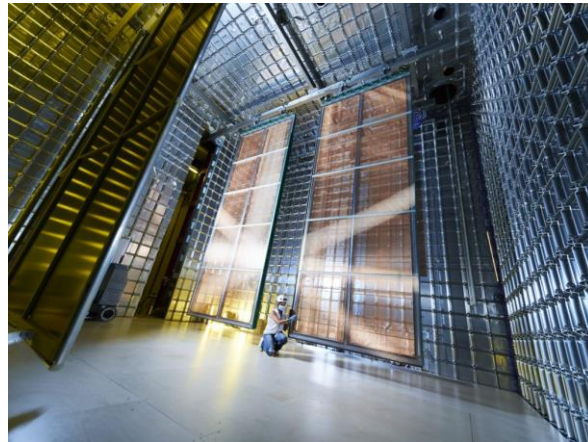
DUNE at Stanford Underground Research Facility 1.5km deep and 1300 km from Fermilab 2026-28  
and 2 Single Phase LAr TPCs 17 kt 68(l) x 14(w) x 12(h) m<sup>3</sup> 1.5 km underground

Far Detector 1

➤ Next step FD3 and FD4 technologies to be decided ex. Theia Liquid Scintillator module 60(r) m x 60(h) m



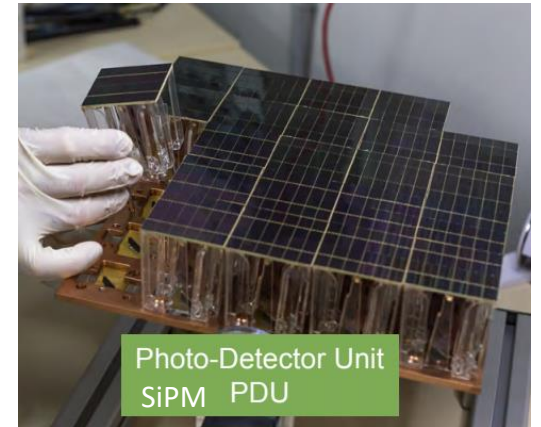
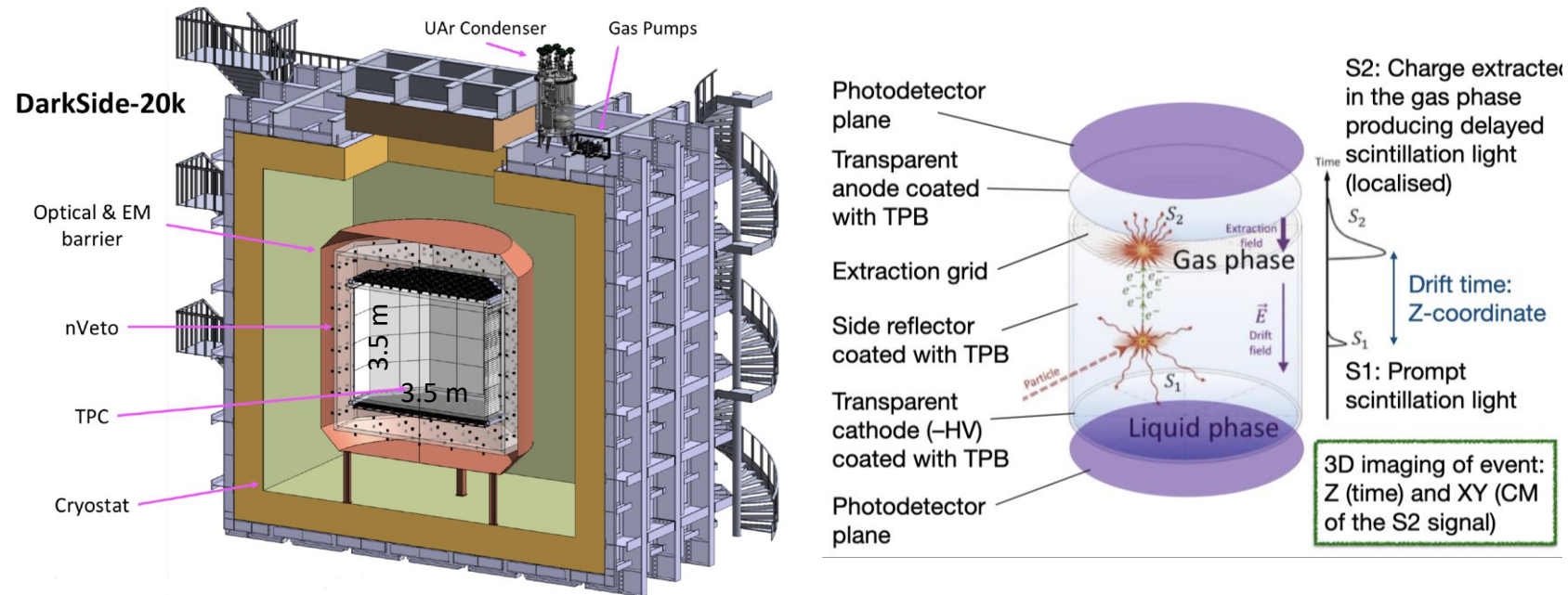
FD1 horizontal anode drift wire readout and SiPMs



FD2 vertical drift PCB anode readout and SiPMs in cathod plane

# Noble liquid TPC Dark Matter

- DarkSide-20k 20t (30 m<sup>3</sup>) double phase LAr\* TPC at Lab. Nat. Grand Sasso, 2025
  - readout both scintillation and ionisation proportionale electroluminescence
- Next step ARGO at SNOLAB (Canada) 300t

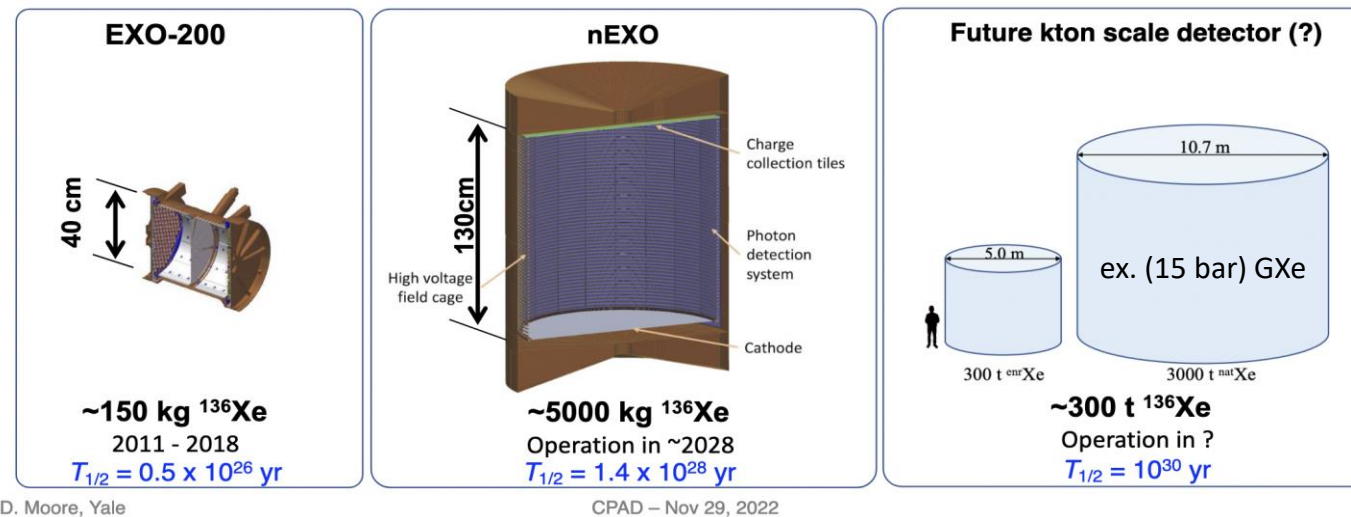


- DARWIN 50t 2.6 x 2.6 m double phase LXe TPC  $\lesssim$  2030?
  - Also using water Cherenkov and Liquid Scintillator to shield TPC

\* Underground extracted, free of <sup>39</sup>Ar radioactive isotope

# Noble liquid TPC $0\nu\beta\beta$

- nEXO 5t single phase LXe single phase TPC (2028)
  - $^{136}\text{Xe}$  decay source and the sensitive medium – readout anode tiles and SiPMs
  - Next generation 300t
    - Supply of Xe is a major challenge
    - High Pressure (15 bar) GXe versus LXe is a compromise between energy resolution and background



- NEXT High Pressure Xenon TPC (2028) with double phase like readout
  - Study daughter  $\text{Ba}^{++}$  combination with fluorescence molecules to tag signal for background rejection

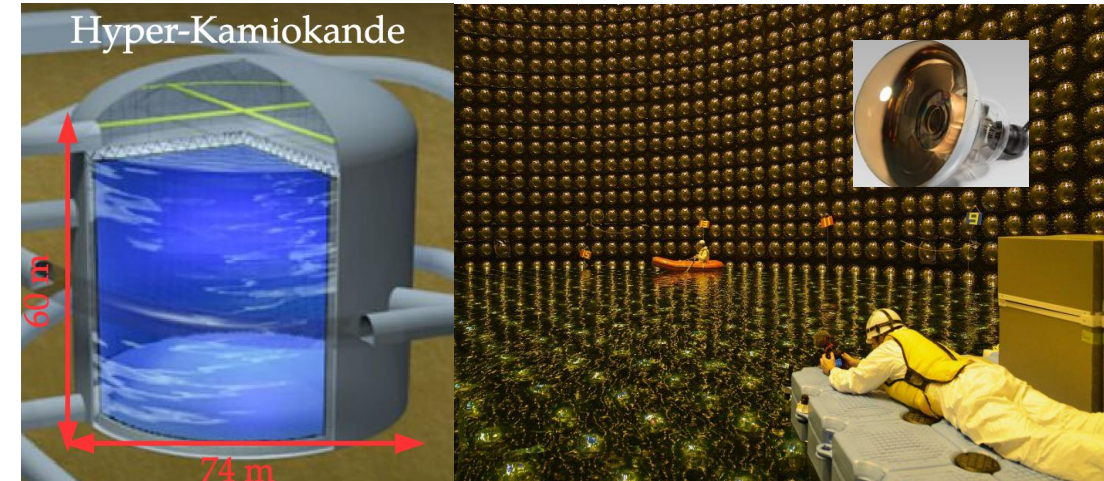


# Water Cherenkov Neutrino

## Hyper-Kamiokande 2027

300 km from JPARC (Tokai, Japan)

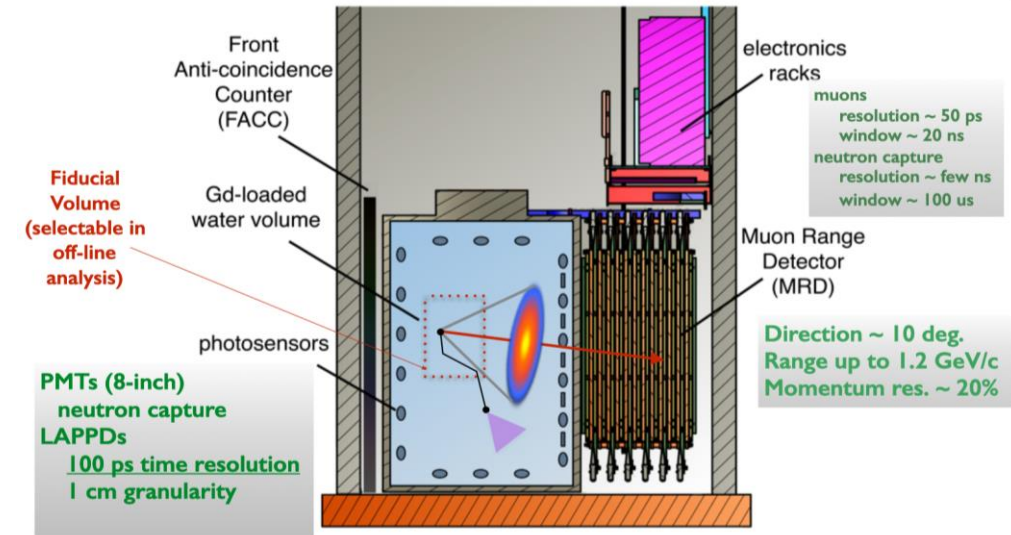
650 m underground 260 ktons ultra pure water Cherenkov,  
readout 40 000 PMT  $\Phi = 50$  cm,  $PDE \approx 30\%$ , 2.6 ns time  
resolution inner tank and 67000 PMT  $\Phi = 20$  cm outer tank



## Accelerator Neutrino Neutron Interaction Experiment at FNAL Booster Neutrino Beam

26 t Gadolinium loaded water Cherenkov\*

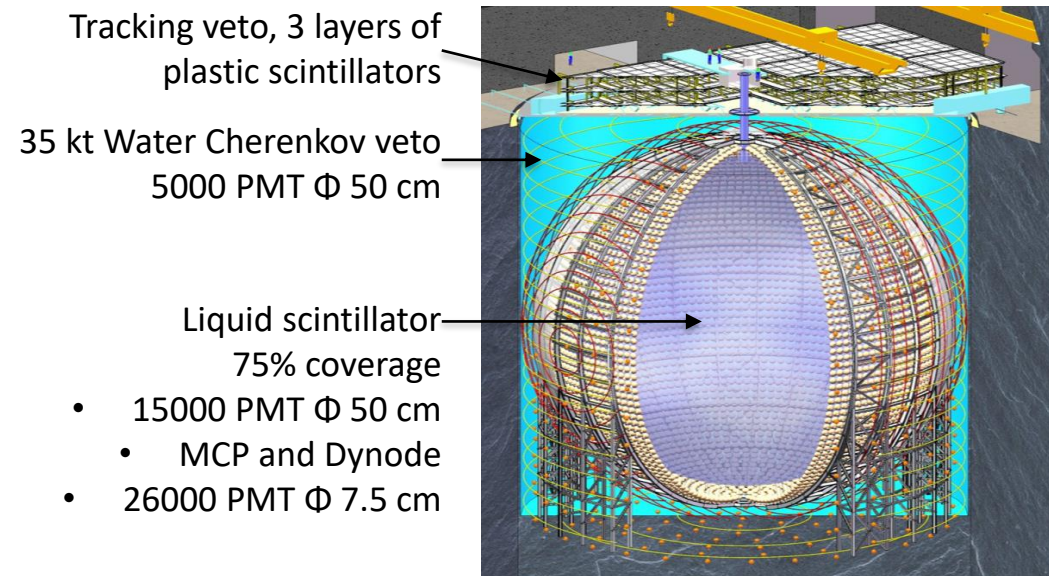
(measure neutrons), Large Area Picosecond PhotoDetectors  
20x20 cm<sup>2</sup>, 60 ps 1 cm position resolution



# Liquide scintillator Neutrino

## Jiangmen Underground Neutrino Observatory China (2023)

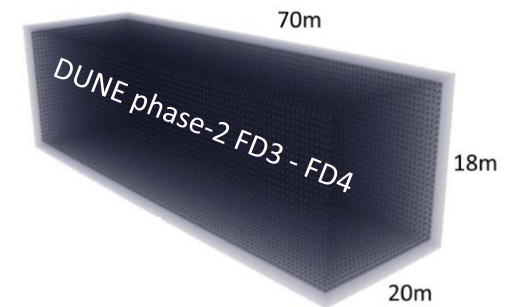
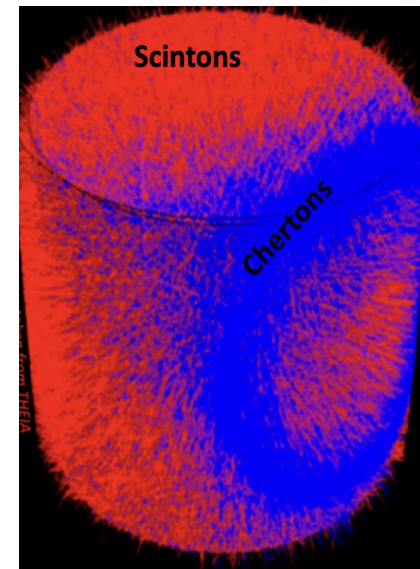
53 km from 2 nuclear power plants, 700 m underground  
20 kt of liquid scintillator, 35 m (d) sphere



## DUNE Phase2 new concept Theia

25kt Water Based Liquid Scintillator

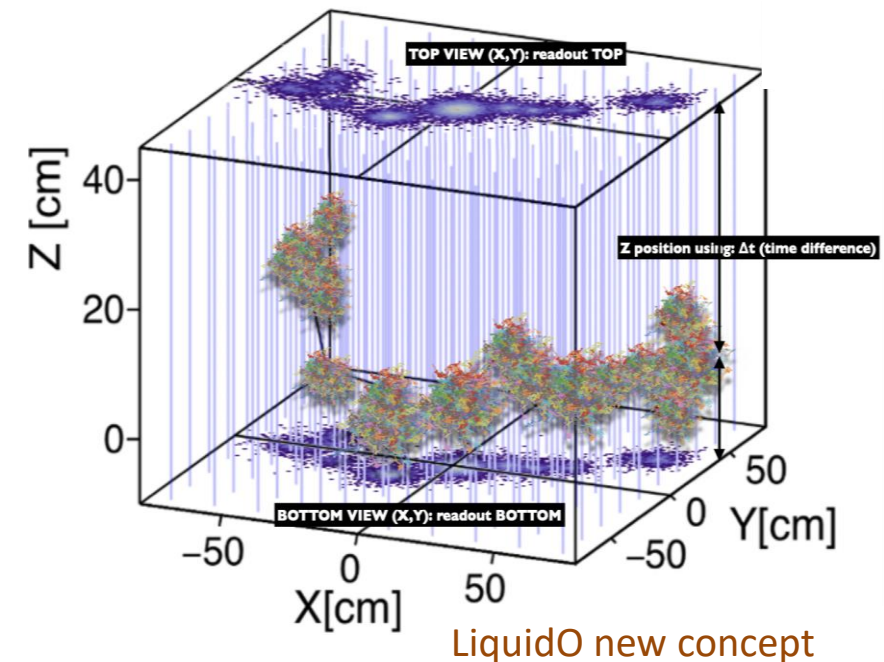
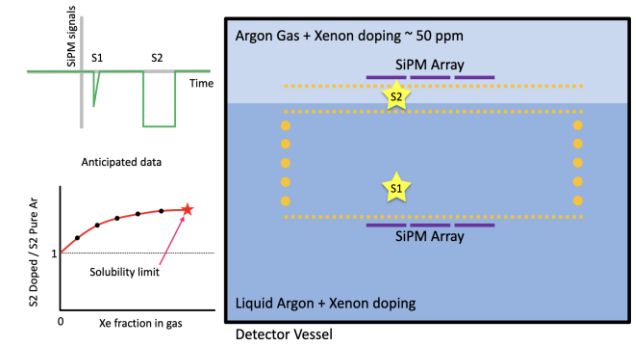
Scintillation high light yield & Cherenkov ring  
directionality, dichroic filters to separate WL on 2  
photosensors or waveform sampling with LAPPD



# R&D Liquid

Increased signal and reduced background

- Noble Liquid (TPC)
  - Xe doping in LAr to increase electro-luminescence in DP
- Liquid Scintillator
  - Develop liquid scintillators with luminophore/quantum dots
  - Develop water-based LS for both scintillation and Cherenkov
    - ex. (Theia DUNE Phase-2 module)
  - Develop opaque liquid scintillator (LiquidO)
- Improve purity of liquid by O(10) to reduce signal absorption
- Improve radiopurity by O(10) to 1000 all materials
  - ex. new concept of crystal/vapor Xe dual phase to eliminate Radon

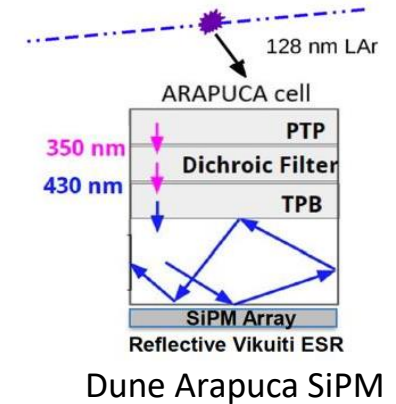
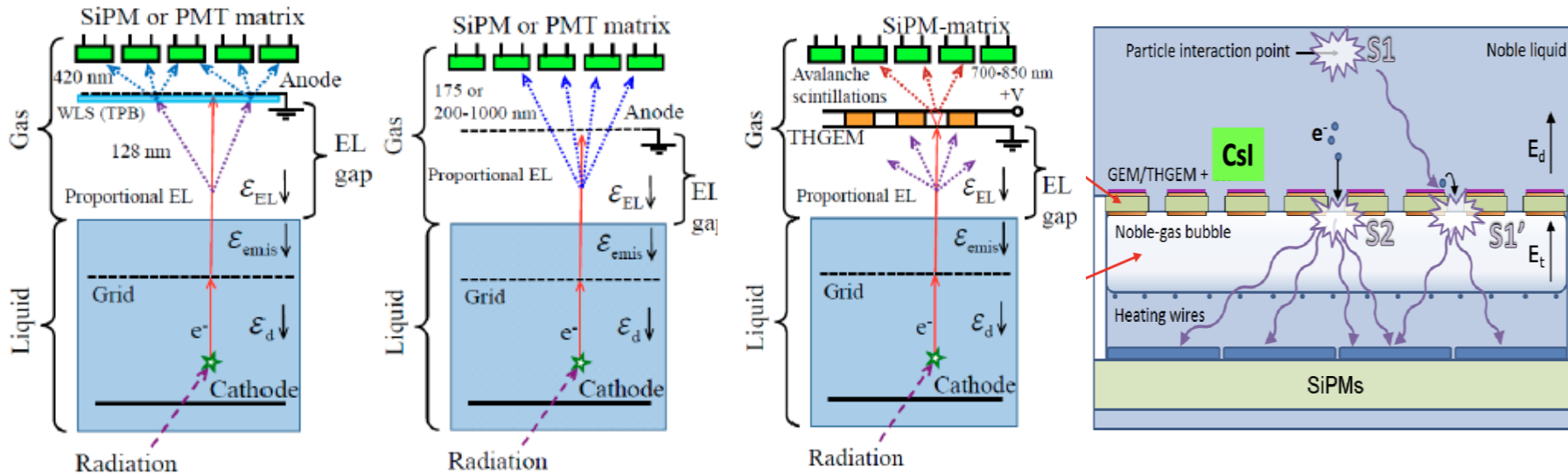




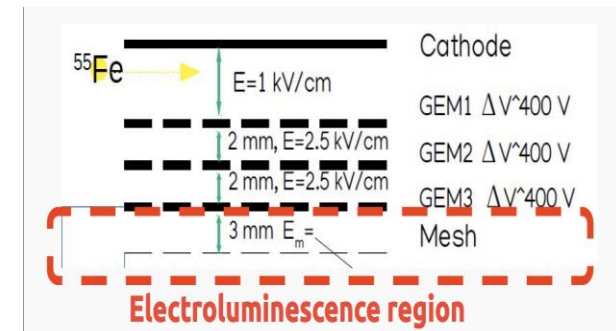
# R&D readout

## Improved photon/ionisation sensitivity and higher granularity

- Photosensors (PMT, LAPPD, SiPM/SPADs, CCD)
  - Improve Wave Length Shifting and/or VUV – NIR Quantum Efficiency
  - Design devices with both ionisation and light sensitivity
- Readout schemes
  - Improved amplification scheme in DP TPC
  - Increase granularity ex CCD with TimePix ASIC for spatial NEXT)



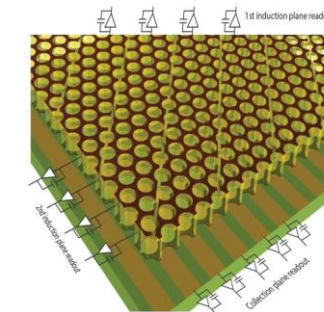
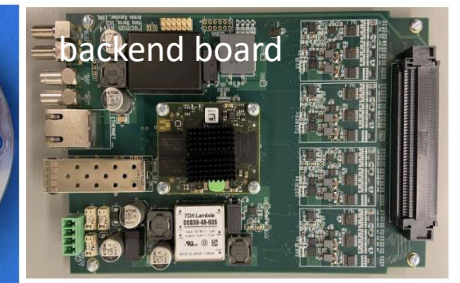
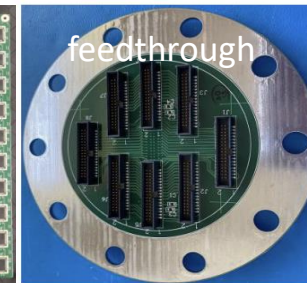
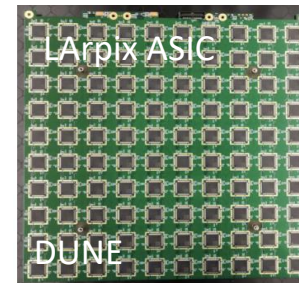
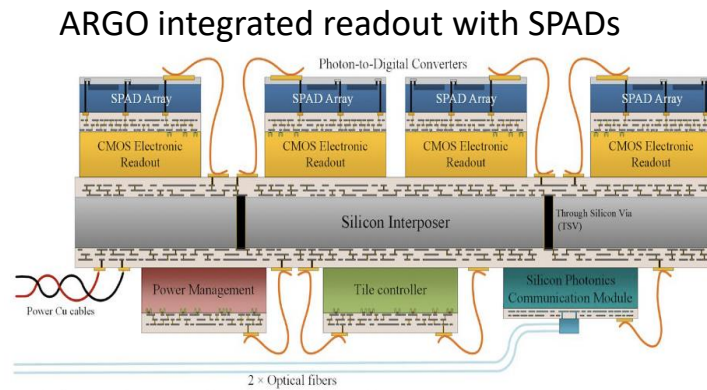
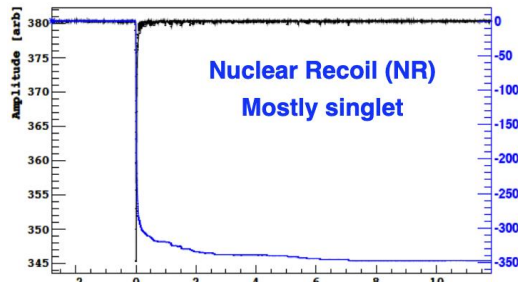
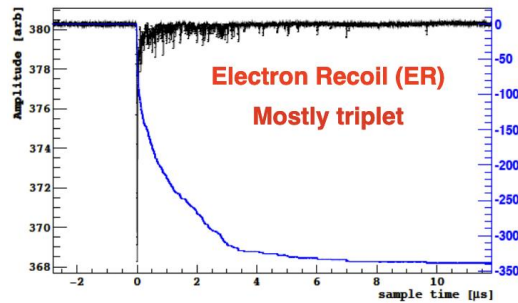
CYGNO directional DM 30 m<sup>3</sup>  
TPC low density HeCF<sub>4</sub>





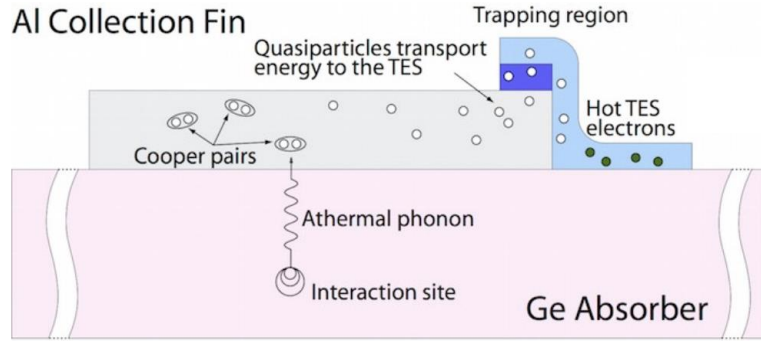
# R&D Electronics

- Electronics
  - Waveform sampling to reject background (potentially to separate Cherenkov/Scintillation)
  - 3D integrated readout operated at cryogenic temperature (including optical transmission)
- Other engineering challenges for volume scaling
  - Cryostat vessels, cryogeny systems, feedthrough, power supplies, monitoring and calibration

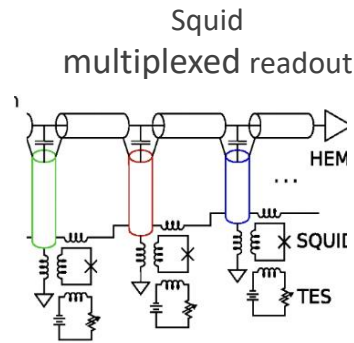
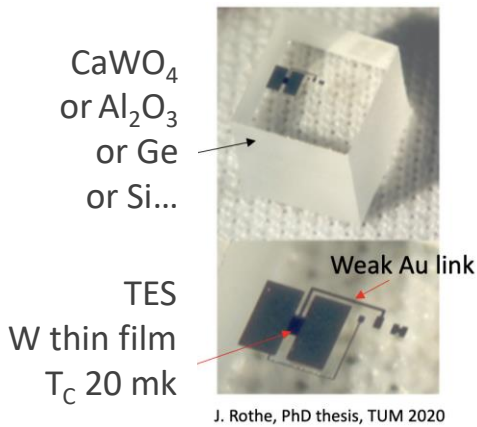




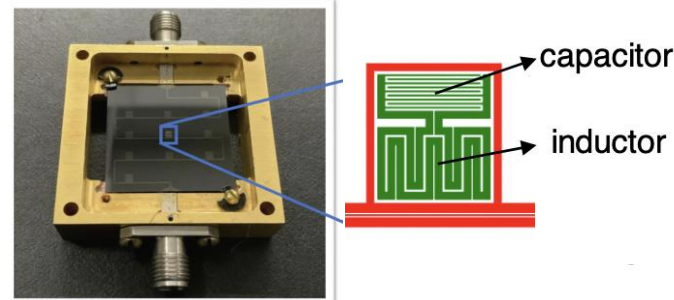
# Phonon detection



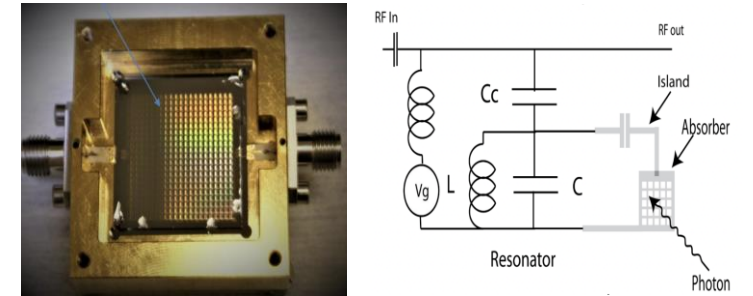
- Transition Edge Sensors loss of superconductivity
- Kinetic Inductance Detector transmission in a LC resonator
  - Quantum Capacitance Detector shift of resonator frequency with change of capacity in a tunnel junction



Single KID 2 cm CRESST 1-10gr

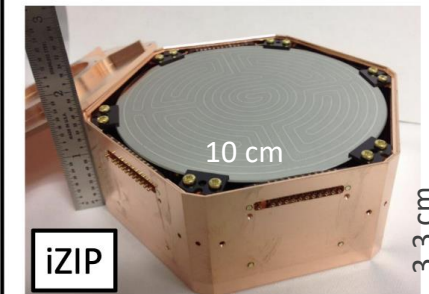


Quantum Capacitance Detector

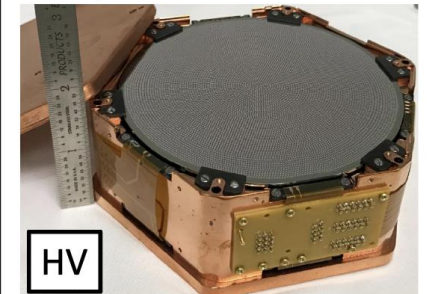


Super CDMS DMS 1.39(0.61) kg kgr

12 phonon, 4 charge channels  
sensitive to  $\geq 5 \text{ GeV}/c^2$  DM  
Ge(Si)  $\sigma_{\text{ph}}=50(25)$  eV  $\sigma_{\text{ch}}=160(180)$  eV



12 phonon channels  
sensitive to sub-GeV DM  
Ge(Si)  $\sigma_{\text{ph}}=10(5)$  eV



R&D to reach sub-ev sensitivity, with larger scale systems

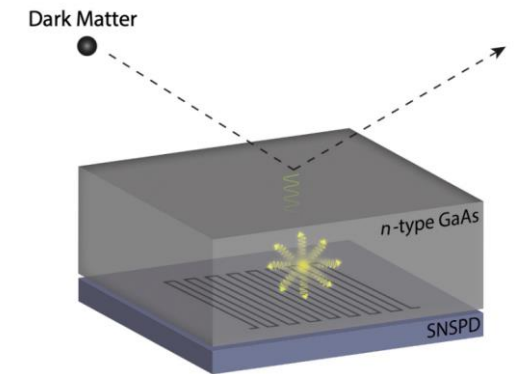
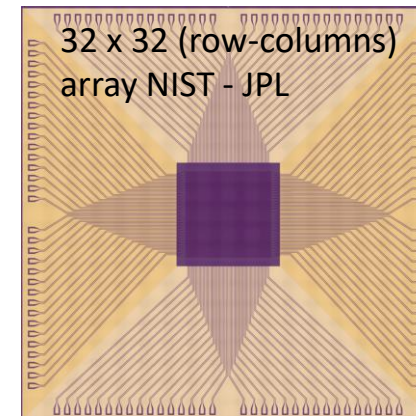
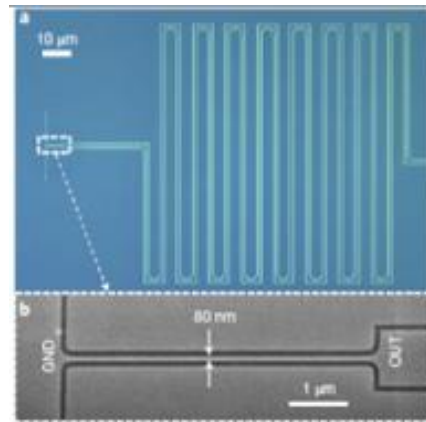
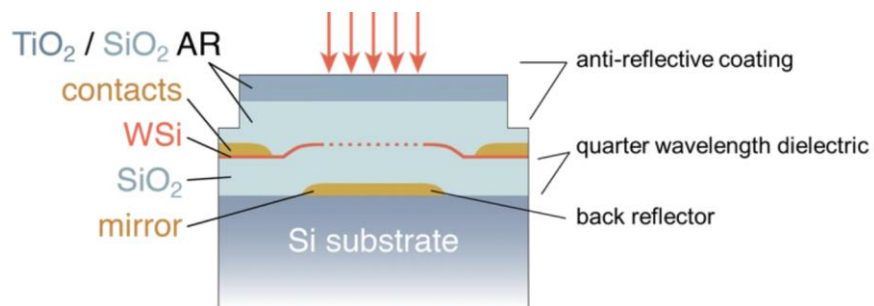
- Superconducting film material (Al, W, TiNx, Nb)
- Configuration of signal measurement structures
- Production process and readout



# Superconducting Nanowire Single Photon Detector

Measure resistance variation of nanowires ( $< 1 \mu\text{m}$ ) at 1–4 K

- Very high QE 10 nm to 10  $\mu\text{m}$  WL, ultralow DCR  $< 10^{-5}$  cps, timing  $\approx 3$  ps, rate capability  $O(1)$  GHz/ $\text{mm}^2$ 
  - Configuration for further improved sensitivity for threshold below 70 meV
  - Larger size sensors accompanied by electronics for channel multiplexing



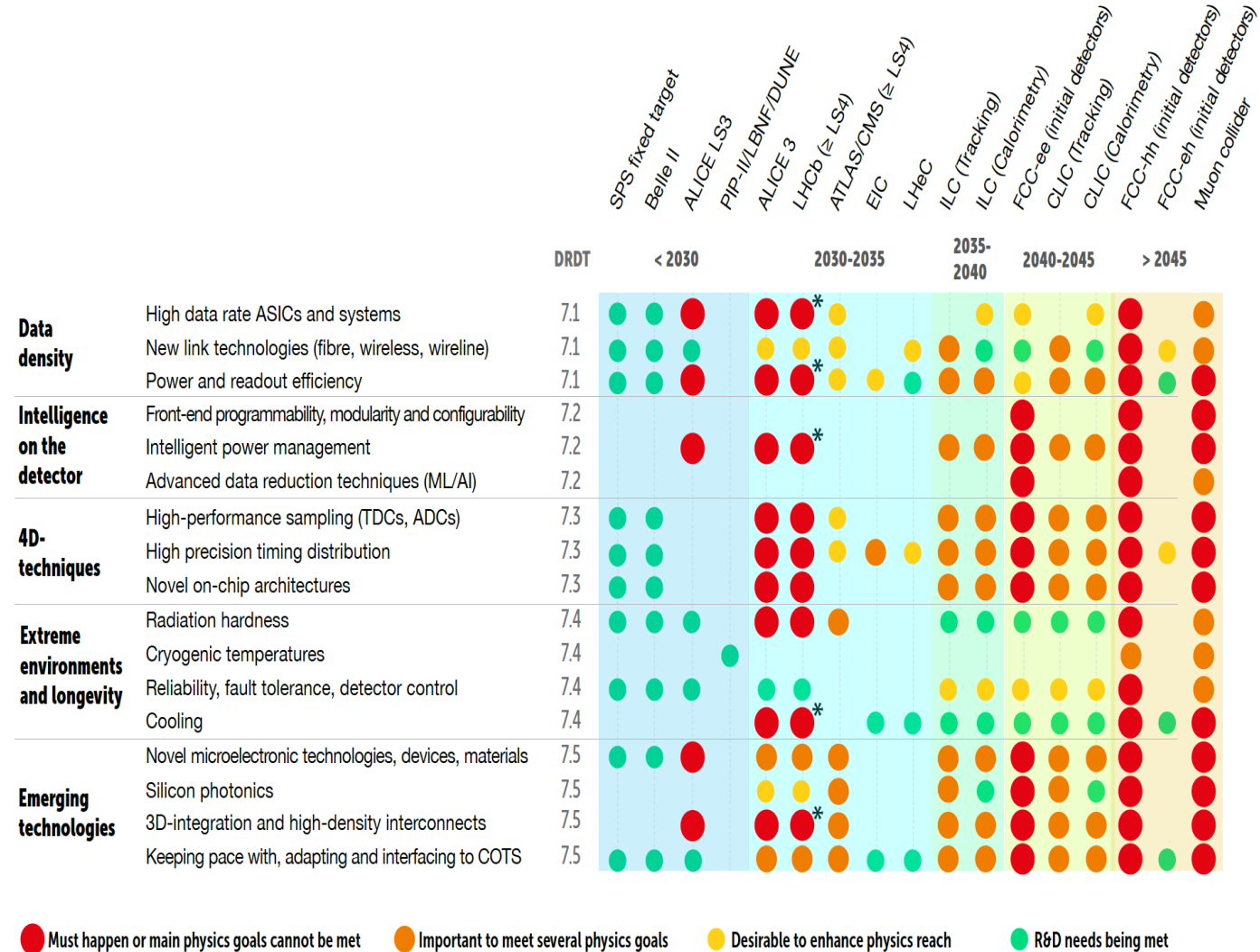


# ECFA R&D roadmap: Electronics

Provide high data density readout and processing in extreme environments,  
 Organise access to technologies, training, help shared developments of complex ASICs  
 Ensure new technology watch

Electronics

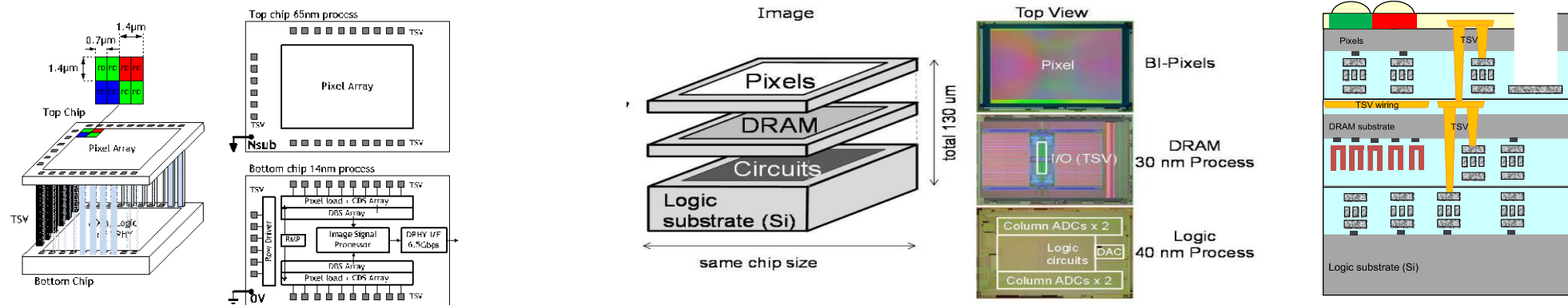
- DRDT 7.1** Advance technologies to deal with greatly increased data density
- DRDT 7.2** Develop technologies for increased intelligence on the detector
- DRDT 7.3** Develop technologies in support of 4D- and 5D-techniques
- DRDT 7.4** Develop novel technologies to cope with extreme environments and required longevity
- DRDT 7.5** Evaluate and adapt to emerging electronics and data processing technologies



● Must happen or main physics goals cannot be met    ● Important to meet several physics goals    ● Desirable to enhance physics reach    ● R&D needs being met

# R&D Electronics

- Transition to deeper ASIC nodes (28 nm R&D started)
  - New readout architectures
    - low power, timing precision, on-detector processing implementing Machine Learning
    - operation at cryogenic temperature
- Develop 3D integrated devices, sensitive element + analogic + digital readout features
- ex. commercial imagers could be an ultimate tracking solution if made radiation hard



Samsung: 1.4 µm pixels in 65 nm & 14 nm Fin-FET (3D transistors) readout , wafer level stacking

Sony (left) 3D layer thinned to 3 µm design for 960 fps  
 Samsung (right) 1.2 µm pixels, 2.5 µm TSV 6.3 µm pitch, 20 nm DRAM, 28 nm logic

## ➤ Technology watch

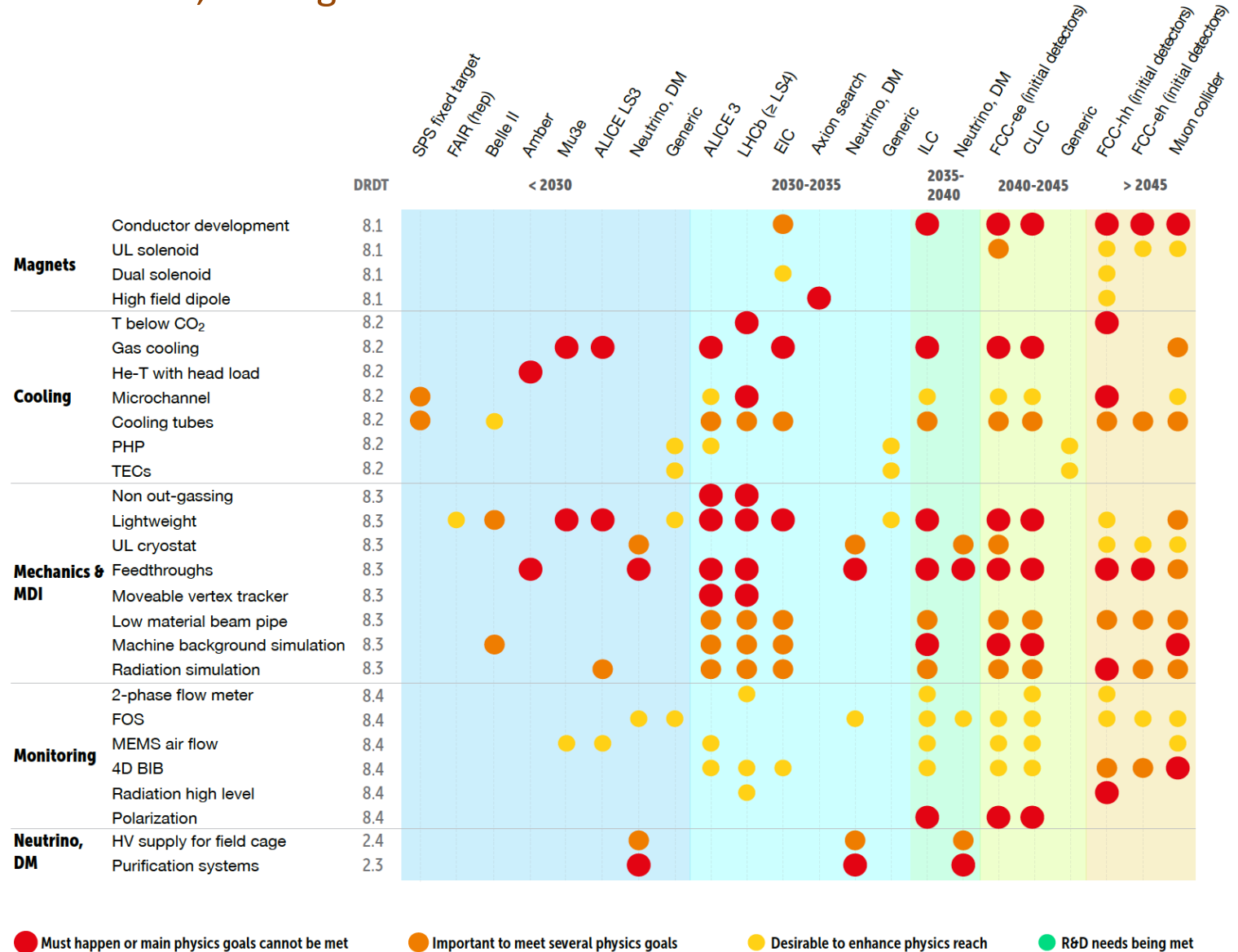
- Photonics data transfer, wireless communication (R&D advancing in WADAPT project)
- New semiconductor materials use in microelectronics industry

# ECFA R&D roadmap: Integration

## Magnets, cooling, mechanical support and structures, management of radiation environment

Integration

- DRDT 8.1** Develop novel magnet systems
- DRDT 8.2** Develop improved technologies and systems for cooling
- DRDT 8.3** Adapt novel materials to achieve ultralight, stable and high precision mechanical structures. Develop Machine Detector Interfaces.
- DRDT 8.4** Adapt and advance state-of-the-art systems in monitoring including environmental, radiation and beam aspects



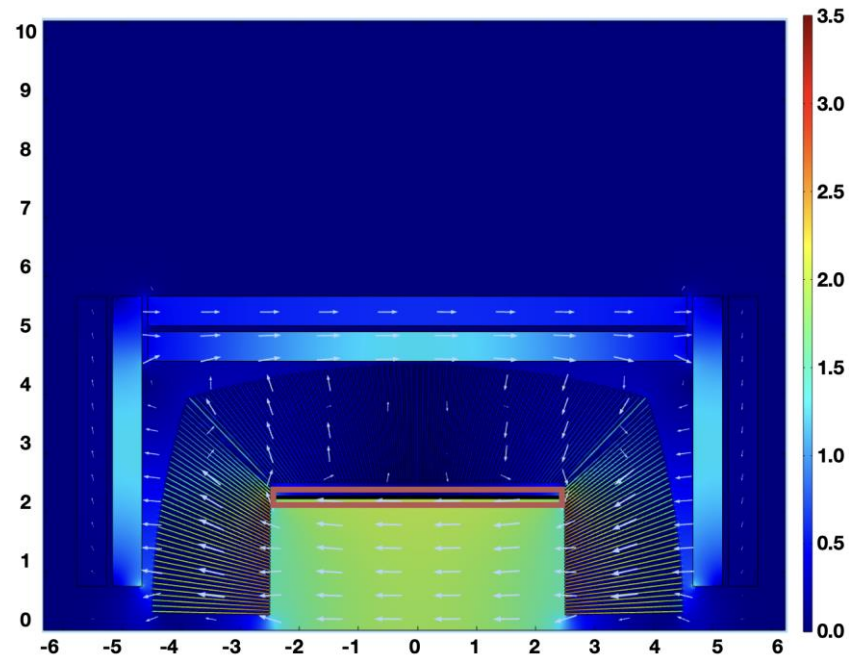
● Must happen or main physics goals cannot be met    ● Important to meet several physics goals    ● Desirable to enhance physics reach    ● R&D needs being met

# Integration R&D solenoid magnets

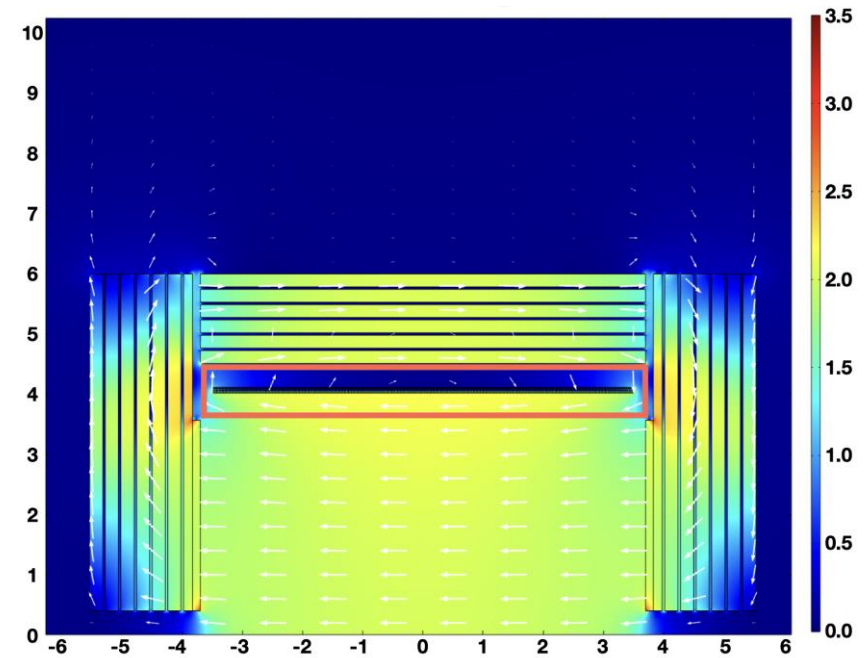
2T thin solenoid for outside calorimetry concepts

R&D to develop high-strength Al-stabilized NbTi superconducting cable and light vacuum vessel

$< 0.5-1X_0$  and  $\approx 0.1 \lambda$



CMS-like solenoid, calorimetry inside  
B up to 4T above Z-peak energy

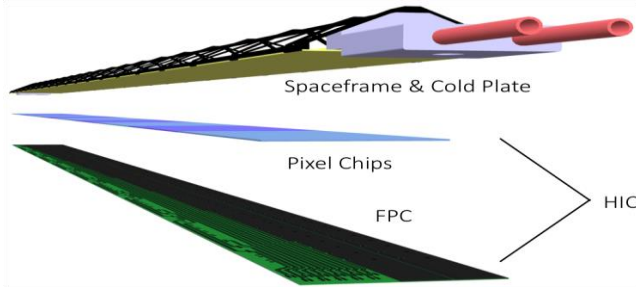




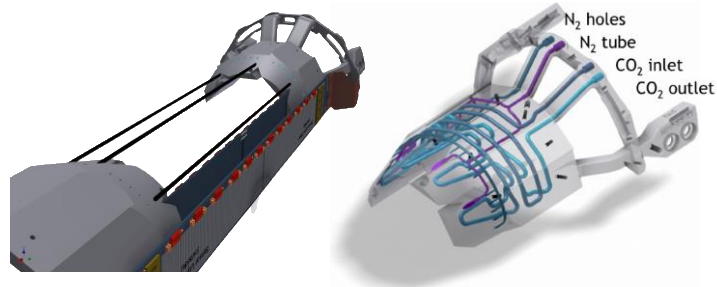
# Integration R&D light stable structures

## x 10 reduction in $X/X_0$ in Vertex Detectors

ALICE ITS2 0.36%  $X_0$ /layer  
 Sensor 15%, PCB 50%  
 Cooling 20% Support 15%



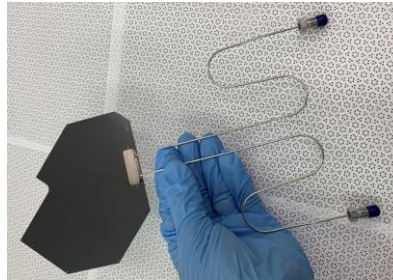
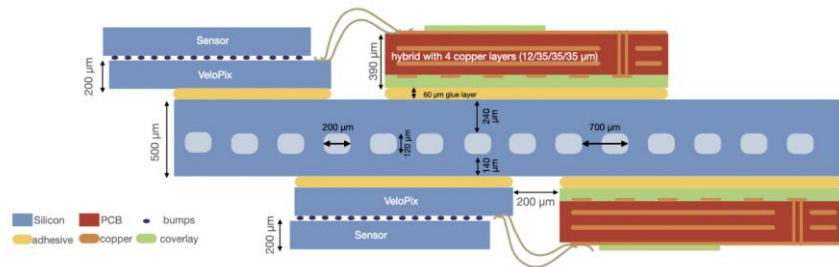
BELLE-II 0.2%  $X_0$  / layer mixed cooling  
 $N_2$  with carbon tubes flow and  $CO_2$



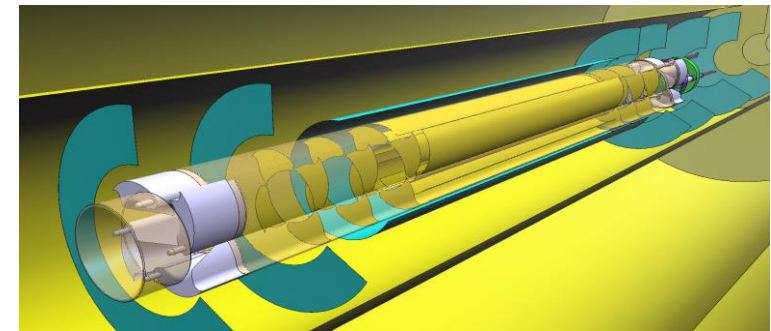
Mu3e average 0.12 %  $X_0$ /layer  
 He cooling, Sensor 0.064 %  $X_0$ ,  
 PCB 0.049 %  $X_0$  Polyimide 0.012  $X/X_0$



LHCb microchannel cooling embedded in Si-sensors

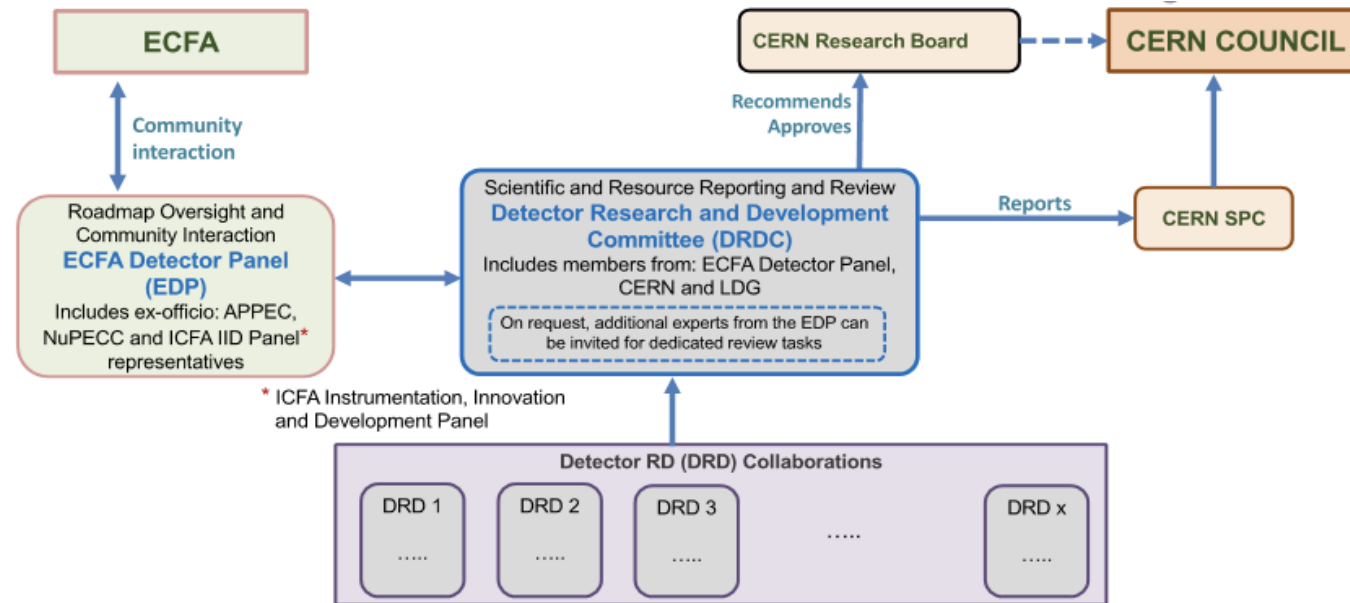


ALICE-3 study retractable layer concept  
 to approach beam at 5 mm inside Beam Pipe



# ECFA R&D roadmap implementation

organize R&D effort in new DRD collaborations (for each areas of the roadmap)  
engage Funding Agencies through MoUs and a dedicated Resources Review Board



DRD proposal prepared for reviewing by DRDC by July 2023

community

consultation process <https://indico.cern.ch/event/957057/page/27294-implementation-of-the-ecfa-detector-rd-roadmap>

New collaborations start to be active beginning of 2024

Funding Agencies sign MoUs in 2024

A propitious time to join instrumentation efforts  
in the new DRD collaborations

